

ULTRA VIOLET IMAGING TELESCOPE (UVIT)

Thermo-Vac Test-Report

UVIT-CDR-01-003.1

**Indian Institute of Astrophysics
Bangalore-560034**

**Test Report
For
Thermo-VAC Test of EM - UVIT Payload**

**Version 1.1
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Documents to be Referred:

1. ASTROSAT-Contamination Control notes V0.1
2. UVIT-990-00001-PRO Rev 1_5 - Functional Test Procedure.
3. UVIT-990-00002-PRO Rev 1_5 - Performance Test Procedure.

1.0 Introduction

This document describes the Engineering Model (EM) Thermo-Vacuum (TVAC) test plan for the UVIT system. The document describes the sequence of tests that will be performed during TVAC testing. As well, the document describes the equipment and facilities required for testing. This document is valid for flight model also wherein the test has to be carried out for acceptance level. The test profile includes the acceptance level testing of flight model.

2.0 Test Plan

2.1 Test Objectives

The objective of the testing is to show that the Engineering Model (EM) version of the UVIT system remains operational and not damaged during and after exposures to qualification levels of thermo vacuum conditions specified by ETLs. This test will also give us an experience and modalities that need to be addressed for achieving the cleanliness and to minimize the contamination levels for flight model payload/spacecraft tests.

2.2 Test Description

Typical test profile and temperature limits for qualification level TVAC test with durations are shown in figure 2.1 and table 2.1.

In vacuum, verifying that the system is operational over repeated hot and cold cycles of prescribed temperatures. See figure 2.1 for the temperature profile.

In vacuum, verifying that the system is operation during a long duration hot and cold dwell temperature cycles.

The UVIT system has supplied items like door, primary and secondary mirror, filter wheel motor and its electronics, HVU (High Voltage Unit), detector and cables. These supplied items have been qualified separately. The other elements are only the telescope tubes, baffles, rings and other metallic structures. The engineering model of the UVIT system has one NUV channel and the mass simulated FUV channel.

During the TVAC test CPU, HVU, EU, FWM and FWDE will be powered ON.

Details of the test to be done on UVIT DS (CPU, HVU and EU), FWM and FWDE during TVAC test is explained in appendix A and B. For TVAC profile of individual subsystems which have undergone TVAC test, please refer Appendix D.

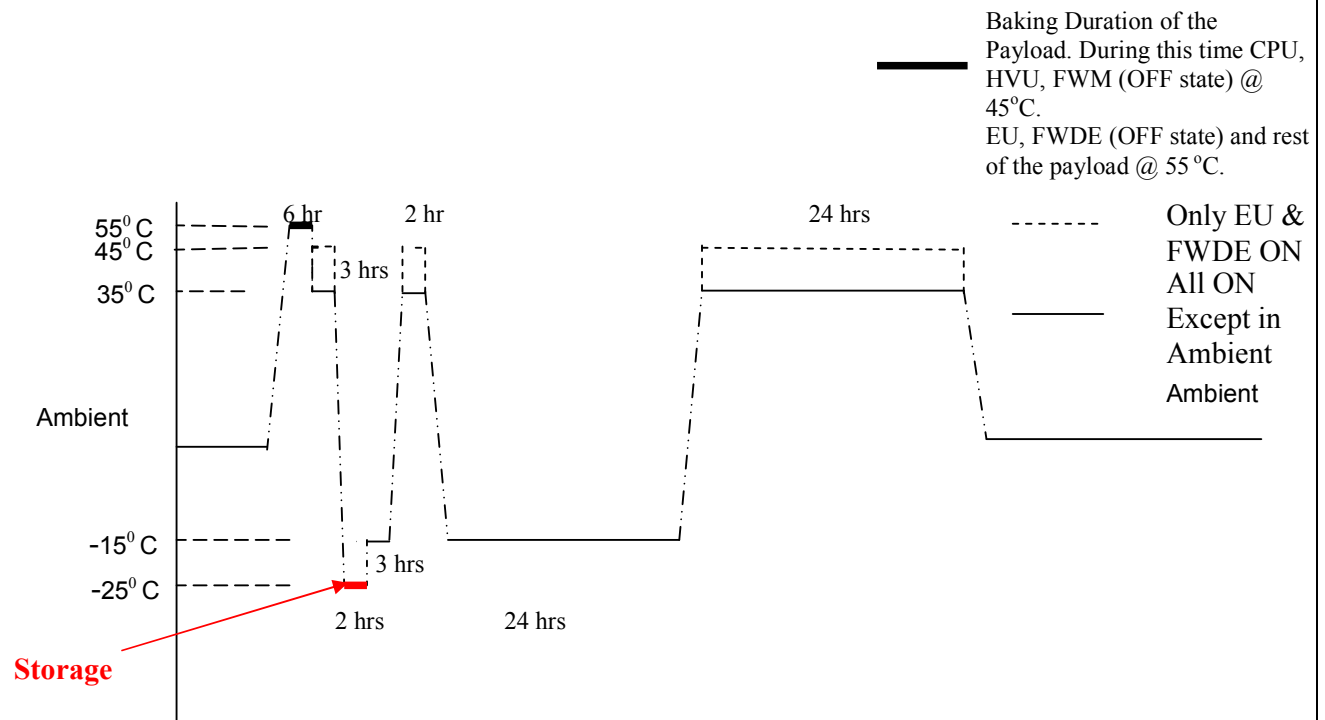


Figure 2.1 EM UVITDS TVAC test Profile (Qualification Levels)

Table 2. 1 List of Environmental Temperature (Qualification) Limits of UVIT Subsystems

Name of Subsystem	Temperature Limits (ON State)		Temperature Limits (OFF State)		
CPU	-15°C	+35°C	-25°C	+45°C	
HVU	-15°C	+35°C	-25°C	+45°C	
EU	-15°C	+45°C	-25°C	+55°C	
FWM	-15°C	+35°C	-25°C	+45°C	
FWDE	-15°C	+45°C	-25°C	+55°C	
PMA	-5°C	+45°C	-5°C	+45°C	
SMA	-5°C	+45°C	-5°C	+45°C	

Critical Temperatures which need to be monitored and control

Name of Subsystem	Temperature Limits (ON State)		Temperature Limits (OFF State)		Temp. Sensor ID	IR Lamp ID
CPU	-15°C	+35°C	-25°C	+45°C	841	L73 to L110
HVU	-15°C	+35°C	-25°C	+45°C	4572	
EU	-15°C	+45°C	-25°C	+55°C	TC 45/46	L 111 to L 114
Door HOP Actuator		+40°C +/- 2 °C		+40°C +/- 2 °C	TC 5/6	L 1 to 12
PMA	-5°C	+45°C	-5°C	+45°C		
SMA	-5°C	+45°C	-5°C	+45°C		

PMA: Primary Mirror Assembly
CDR-June-11)

SMA: Secondary Mirror Assembly (ref: UVIT-

2.3 Test Facility Aspects

The tests are planned in 6 mtrs CATVAC chamber at ISITE test facilities. The facility is chosen because of the better clean room environment. The chamber is in the clean room of 1 lakh class. However, it has been observed that cleanliness achieved in terms of particle count is better than 15000 with controlled man-material movement. The facility is equipped with TCQM equipment (for molecular contamination measurements) and also Residual Gas Analysis system within the chamber.

2.3.1. Test Methodology

In view of the high cleanliness and contamination requirements of the payload, it is required to adopt the test methodology of keeping the Shroud Temperature always at a constant Low temperature of -80 deg C and achieve the required differential temperature limits on the payload subsystems by using the combination of Heaters and the IR lamps.

The chamber need to develop a vacuum level better than 1×10^{-6} mbar as part of standard test specifications for performing the TVac tests.

2.3.2 Thermal Test Contingency Procedures/Safety Measures

The vacuum level requirements and the contingency procedures/safety measures shall be same as the one used for spacecraft level tests. The details of the same are reproduced below.

Sl. No.	Types of failures	Consequences or impact on temperature control	Contingency measures
1.	KEB power failure	Lamps/heaters - off	<ul style="list-style-type: none">Generator power is available within 10 minutes. Power controllers will be powered using DG supply. DACS is connected to UPS.
		Cooling of P/L. Marginal impact on PAYLOAD package temperatures for short durations. However, it is critical during cold cycle/soak.	<ul style="list-style-type: none">When KEB power failure occurs, the power supplies becomes off. It is recovered after power returns/power availability.
2	KEB power and UPS system	Lamps/heaters - off	<ul style="list-style-type: none">Generator power is available within 10 minutes through same electrical points. Thermal power supplies will be powered using DG supply.
		Cooling of P/L ,it is critical during cold cycle/soak.	<ul style="list-style-type: none">When KEB power failure occurs, the power supplies becomes off. It is recovered after power returns/ power availability.

Sl. No.	Types of failures	Consequences or impact on temperature control	Contingency measures
3	Power Supply failures		
	Case-A: Power supply off/output is zero.	Local cooling in the heater/IR lamp zone.	<ul style="list-style-type: none"> • Connection of heater/IR lamps to spare power supply. • During rectification, nearby heaters/IR lamps will be used for temperature Control.
	Case-B: Power supply is overloading	Localized hot spot may be created if set current limit is very high. Serious case for skin bonded heaters.	<ul style="list-style-type: none"> • Re-set the power supply. • Put off the AC mains of power supply, if it is not possible to re-set the power supply
4	Failure of monitored T/C channel of a heater zone	No impact	<ul style="list-style-type: none"> • Select the redundant T/C channel.
5	<ol style="list-style-type: none"> 1. TPSU failure. 2. Failure of remote operation of PCS 3. DACS failure etc. 	T/C monitoring is affected. Temperature control is affected	<ul style="list-style-type: none"> • Rectify the fault. • Test heaters/IR lamps operation to be done judiciously using thermistor temperature sensor.

Sl. No.	Types of failures	Consequences or impact on temperature control	Contingency measures
6	Test heater/IR lamp failure	Failed heater/IR lamp cannot be used	Nearby heaters/IR lamps will be used to maintain the temperatures.
7	Sub-systems' temperature exceeding the upper limit.	Subsystem temperature more than upper acceptance temperature limit.	Immediately reduce the nearby IR lamp/heaters power to safe value of temp. Inform to test director nominated by Chairman, Thermovac test Committee/PD -ASTROSAT.
8	Subsystems' temperature exceeding the lower acceptance limit.	Subsystem temperature lower than the lower acceptance temperature limit.	Increase the IR lamp/heater power to the area. Nearby IR lamp/heater power may also be increased judiciously. Inform and consult the test director nominated by Chairman, Thermovac test Committee/PD -ASTROSAT.
9	Chamber leak/vacuum failures	More heat leak/loss from S/C Cooling of PAYLOAD	PAYLOAD temperatures will be maintained by increasing power to heaters/lamps to compensate the heat leakages.
10	Rise in shroud temperature	PAYLOAD temperature goes up.	Power to heaters/lamps will be reduced to maintain the temperatures. PAYLOAD load will be reduced, if required
11	PAYLOAD goes off	No thermistor temp. Data No onboard heaters control Cooling of PAYLOAD	PAYLOAD thermal health will be monitored and maintained through thermal test instrumentation except for CPU,HVU and motor. Voltage to lamp & test heaters will be maintained judiciously to keep the components in safe limits.

2.3.3. Contingency Procedures/Safety Measures During Payload Performance Tests

The payload powering and the performance verification tests will be done using the Ground Support Equipment (GSE). The GSE will be operated on UPS supplied by the facilities. The payload performance tests will be done after achieving the respective stabilized temperature limits during short cycles of Hot and Cold and also during the Long Hot & Cold cycles.

UVIT detector System need to be switched ON or Operated only at vacuum level better than 10^{-6} mbar. Payload will be switched OFF, in case of any power failure at facility, which may result in drop in vacuum level below the specified value (10^{-6} mbar).

2.4 Test Sequence

2.4.1 Cable Bake Out

Before putting the cable harnesses into the Thermo Vacuum chamber for testing they must be vacuum baked. Table 2.2 below lists the cables to be vacuum baked.

Table 2. 2 Harness Assembly for Vacuum Bake Out

S. No.	Quantity	Description	Part Number
1.	1	CPU-PB Harness Assembly (1 mt)	UVIT-952-00007-CBL-01
2.	1	HVU-PB Harness Assembly (1 mt)	UVIT-952-00009-CBL-01
3.	1	PB-EU Flange (2.2 mt, CPU)	
4.	1	PB-EU Flange (2.2 mt, HVU)	
5.	1	EU-TVAC Flange (3mt, DHU)	
6.	1	EU-TVAC Flange (3mt, BMU, discrete)	
7.	1	EU-TVAC Flange (3mt, BMU, 1553B)	
8.	1	EU-TVAC Flange (3mt, Raw Power)	
9.	1	FWM with Harness	
10.	1	Harness for FWM signals	
11.	1	Harness for thermal control	
12.	1	FWDE-TVAC Flange	
13.	1	Circular harness for Thermistors	
14.	1	Circular harness for FWDE	
15.	1	Circular harness for DHU	
16.	1	Circular harness for Power and Discrete signals	
17.	1	Circular harness for 1553B	

2.4.2 Test Thermo Vacuum Chamber Bake Out and Cleanliness Check

The chamber shall be baked at the highest possible temperature, say at 60 C, and be monitored by TCQM (operated at – 20 C). Baking shall continue till TCQM shows a rate $< 8.71 \times 10^{-12} \text{ gm/cm}^2/\text{sec}$, and a rate of change in rate of $< 3.03 \times 10^{-16} \text{ gm/cm}^2/\text{sec}^2$ for 8 hrs.

TV cleanliness needs to be verified prior to placing ASTROSAT parts inside. Therefore a test thermal cycle is performed, at plateau temperatures of + 40 C for 12 hrs and then a plateau temperature of – 20 C for 12 hrs with a witness sample (Mg F2 window) placed in the chamber for monitoring; the witness sample is used after its transmission, in 120 – 180 nm range has been measured After this test thermal cycle, the witness sample is measured again for its transmission. Any reduction to < 95% of the original transmission is an indication of potential contamination in the chamber.

Finally the chamber was baked in 2 phases. In the first phase the shroud was baked at 60 deg C for 36 hours with all the fixtures and IR Lamp cage assembly inside the chamber. TCQM measurements were made by keeping the cold finger at - 20 deg C to assess the contamination level inside the chamber.

In the second phase 2 witness sample window (MgF2) were placed inside the chamber and the chamber was baked at +40 deg C for 12 hours and at -20 deg C for 12 hours.

Results of the witness sample show the transmission loss is less than 5% which is an acceptable number. Hence the chamber is cleared for payload tests.

Remark for FM TVAC Test of UVIT

In the second phase 2 witness sample window (MgF2) were placed inside the chamber and the chamber was baked at +40 deg C for 84 hours (3.5 days) and at -20 deg C for 84 hours (3.5 days).

Results of the witness sample show the transmission loss is less than 2% which is an acceptable number. Hence the chamber is cleared for payload tests.

2.4.3 Test Flow

The UVIT payload [CPU, HVU, EU, FWM and FWDE] is placed in the test thermal vacuum chamber and will be operational during full TVAC test.

1. Conduct a visual inspection and electrical functional check of CPU, HVU, EU, FWM and FWDE at CREST.
2. Tie Plates between the tubes of NUV and Mass model are to be removed at CREST for easy removal of the main baffles of the mass model at ISITE.
3. Pack UVIT Payload (with the required N₂ supply), EU, FWDE, EGSE and FWM test setup properly at CREST. Please refer '*procedure-cum-log-UVIT-transport-and-handling.xls*' for full procedure of packing the UVIT Payload.
4. Pack necessary tool kit (spanner set, torque wrench, screw driver set, allen key set, packing tape, extension boards, cutting pliers, cable ties, gloves, ESD wrist strap, electrical tape, copper tape, kapton tape, 3-pin plugs) to be carried along with the payload.
5. Transport UVIT payload to ISITE TVAC facility. Monitor Shock watch monitors during transport. Also check the N₂ supply also.
6. Unload UVIT payload and other items at ISITE. [Request in advance to project office to provide manpower and logistics (crane, forklift etc) for unloading the payload and other items at ISITE facility].
7. Don't remove N₂ supply till it goes to TVAC.
8. Remove Main Baffles from mass model after loading the payload on TVAC mounting trolley.
9. Conduct a visual inspection off all the boxes. Then open all boxes and arrange the items to conduct a functional and performance test on UVIT detector subsystem and FWM as mentioned in Appendix B and Appendix A respectively.
10. After confirming the cleanliness of TVAC chamber, load UVIT payload in it.
11. Connect all the cables required for testing during TVAC test.
12. Close the chamber door but do not pump down.
13. Conduct Full Performance test of UVITDS, FWM.
14. Place the UVITDS, FWM in OFF state.
15. Start the evacuation of chamber to the required vacuum level.
- 16. Hot non-Operational (also HVU venting)**
 - a. Maintain the minimum value of the CPU temperature to 45 +0/-2°C
 - b. Turn ON EU heater to achieve EU temperature of 55 +0/-2°C with CPU temperature of 45°C +0/-2°C.

- c. Turn ON FWM heater to achieve FWM temperature of $45 \pm 2^{\circ}\text{C}$.
- d. Turn ON FWDE heater to achieve FWDE temperature of $55 \pm 2^{\circ}\text{C}$.
- e. **Maintain CPU, HVU & FWM at $45^{\circ}\text{C} \pm 2^{\circ}\text{C}$ and EU & FWDE at $55^{\circ}\text{C} \pm 2^{\circ}\text{C}$ for 6 hours.**

17. Hot Operational 1

- a. Decrease the maximum temperature of the CPU, HVU & FWM to **$35 \pm 2^{\circ}\text{C}$** .
- b. Adjust EU & FWDE heater power as necessary to achieve EU & FWDE temperature of $45 \pm 2^{\circ}\text{C}$ with CPU, HVU & FWM temperature of 35°C .
- c. Conduct a full performance test of UVITDS (CPU, FWM & HVU at 35°C and EU & FWDE at 45°C), (appendix B.1, A respectively).
- d. Maintain EU Temperature 45°C , by adjusting the heater.
- e. Place UVITDS, in “Low Power” State, FWM in OFF and FWDE in ON state.
- f. Plateau minimum duration 3 hr.
- g. Put UVITDS (CPU, HVU and EU), and FWDE in OFF state.

18. Cold Non Operational

- a. Reduce the maximum value of the UVITDS (CPU, HVU and EU) and FWM & FWDE temperatures to $-25 \pm 2^{\circ}\text{C}$, allow to stabilize.
- b. Leave UVIT Detector Subsystem “Off”.
- c. Plateau minimum duration 2 hrs.

19. Cold Operational 1

- a. Increase the UVITDS (CPU, HVU and EU) and FWM & FWDE temperatures to $-15 \pm 2^{\circ}\text{C}$.
- b. Conduct a full performance test of UVITDS, FWM and FWDE (appendix B.1, A respectively).
- c. Place UVITDS in “Low Power” State, FWM in OFF and FWDE in ON state.
- d. Plateau minimum duration 3 hrs.
- e. Put UVITDS, and FWDE in OFF state.

20. Hot Operational 2

- a. Increase the maximum temperature of the CPU, HVU & FWM to $35 \pm 2^{\circ}\text{C}$.
- b. Power and adjust EU & FWDE heater power as necessary to achieve EU & FWDE temperature of $45 \pm 2^{\circ}\text{C}$ with CPU temperature of 35°C .
- c. Conduct a full functional test of UVITDS, FWM and FWDE (appendix B.1, A respectively).
- d. Maintain EU Temperature 45°C , by adjusting the heater.
- e. Maintain FWDE temperature $45 \pm 2^{\circ}\text{C}$.
- f. Place UVITDS, in “Low Power” State, FWM in OFF and FWDE in ON state.
- g. Plateau minimum duration 2 hr.
- h. Put UVITDS, and FWDE in OFF state.

21. Cold Operational Long Duration

- a. Decrease the UVITDS (CPU, HVU and EU) and FWM & FWDE temperatures to $-15 -0/+2^{\circ}\text{C}$.
- b. Conduct a full performance test of UVITDS, FWM and FWDE (appendix B.1, A respectively).
- c. Payload team may conduct testing on the Subsystem. This could include a long duration test with NUV channel imaging.
- d. During this plateau, perform the following tests recommended after EM TVac:
 - Perform long imaging runs of at least 15 minutes for both the hot and cold thermal plateaus to achieve thermal balance at the STAR250 (note that GSE limitations will not permit continuous logging of image data for this test and so data logging will have to be turned on and off).
 - Record the time and all temperatures including the temperatures reported by telemetry as well as the amount of power going into the system when thermal balance is reached.
- e. **Place UVITDS in “Stand By” State, FWM in OFF and FWDE in ON state.**
- f. Plateau minimum duration 24 hrs.

22. Hot Operational Long Duration

- a. Increase the maximum temperature of the CPU, HVU & FWM to $35 -0/+2^{\circ}\text{C}$.
- b. Power and adjust EU & FWDE heater power as necessary to achieve EU & FWDE temperature of $45 -0/+2^{\circ}\text{C}$ with CPU temperature of 35°C .
- c. Conduct a full performance test of UVITDS, FWM and FWDE (appendix B.1, A respectively).
- d. Maintain EU & FWDE Temperature 45°C , by adjusting the heater.
- e. Payload team may conduct testing on the Subsystem. This could include a long duration test with NUV channel imaging.
- f. During this plateau, perform the following tests recommended after EM TVac:
 - Perform long imaging runs of at least 15 minutes for both the hot and cold thermal plateaus to achieve thermal balance at the STAR250 (note that GSE limitations will not permit continuous logging of image data for this test and so data logging will have to be turned on and off).
 - Record the time and all temperatures including the temperatures reported by telemetry as well as the amount of power going into the system when thermal balance is reached.
- g. **Place UVITDS, in “Stand By” State, FWM in OFF and FWDE in ON state.**
- h. Plateau minimum duration 24 hr.
- i. Put UVITDS, and FWDE in OFF state.

23. Returning to Ambient temperature and Pressure

- a. Increase the UVITDS (CPU, HVU and EU) and FWM/ FWDE temperature to 23 +/- 2°C (ambient).
 - b. Vacuum break or venting of chamber will be initiated using dry nitrogen of 99.95% purity. This purging will be done 2 times to ensure condensation doesn't occur to any subsystem under test.
 - c. Conduct a full functional test of UVITDS, FWM and FWDE (appendix B.1, A respectively).
 - d. Conduct a full performance test of UVITDS, FWM and FWDE (appendix B.1, A respectively).
 - e. Open Chamber and unload UVIT Payload.
 - f. Conduct visual inspection.
24. Remove all the cables from TVAC chamber and pack all items (EGSE, FWM test setup etc) to ship back to CREST, IIA.
25. Assemble Dummy baffles to the payload.
26. Connect the N2 Purging to the payload.
27. Cover the UVIT payload with covers & put into the inner container of transport container.
28. Pack all the tools, slings, clean room dresses.
29. Ship back all the items with payload to CREST, IIA.
30. After coming to CREST, IIA, unpack all the items. Conduct visual inspection.
31. Clean all the items with IPA.
32. Wipe the payload with Spectroscopic grade IPA.
33. Conduct performance test on UVITDS and filter wheel drive mechanism.

3.0 Precaution and Contamination Control:

The UVIT system is a very sensitive system. All contaminations are to be avoided. A clean environment is required to be maintained. Even while down loading of UVIT the area has to be clean. Proper identification of clean area has to be done. The system requires continuous purging with nitrogen. Adequate precaution is required to be taken by covering the system before and after test with a proper cover. Each time a fresh cover has to be used. Reuse of cover is forbidden. Another precaution is that the UVIT system is ESD (Electro Static Discharge) sensitive. Necessary precautions with proper ESD protection are to be taken while handling the system.

During the test, it should be ensured that the components like detector/ HVU/any other component does not exceed the operational limit specified. Adequate precautions are to be taken for proper temperature maintenance.

CPU is very critical subsystem whose temperature to be maintained strictly. Temperature limits should be maintained at 35 +0 / -2 °C during its operation.

UVIT is prone to contamination in TVAC chamber at ISITE. A guideline to control contamination for ASTROSAT has been already issued from ASTROSAT project office. Please refer document "***ASTROSAT-Contamination Control notes V0.1***" for the details.

AS a necessary precaution, the TV chamber shall be free of any silicon compounds/greases, and the O'rings shall be coated with a thin layer of LVP Crytox grease of Dupont. Inside of the chamber shall be cleaned with lint free cloth with high grade Acetone etc. to remove any traces of contaminants.

3.1 Procedure for TQCM measurement

1. TQCM needs to maintain at -20°C during measurement time and at +60°C during baking and when not measuring the contamination.
2. Measurement of TQCM shall be made for at last 4 hours at every 15 minutes, of baking and first HOT operation cycle (combined). On completion of contamination measurements, the temperature of the TQCM need to be raised to +60°C to ensure the TQCM surface is clean for the next measurements.
3. Next set of measurement will be done at last 8 hours of Long HOT cycle.

3.2 Contamination assessment using Witness Samples (MgF₂ window)

Two samples of MgF₂ windows are placed in TVAC chamber to asses the cumulative contamination 7 days empty chamber before test and during the test. These samples will be taken out after completion of tests and transmission loss will be measured at IIA facility.

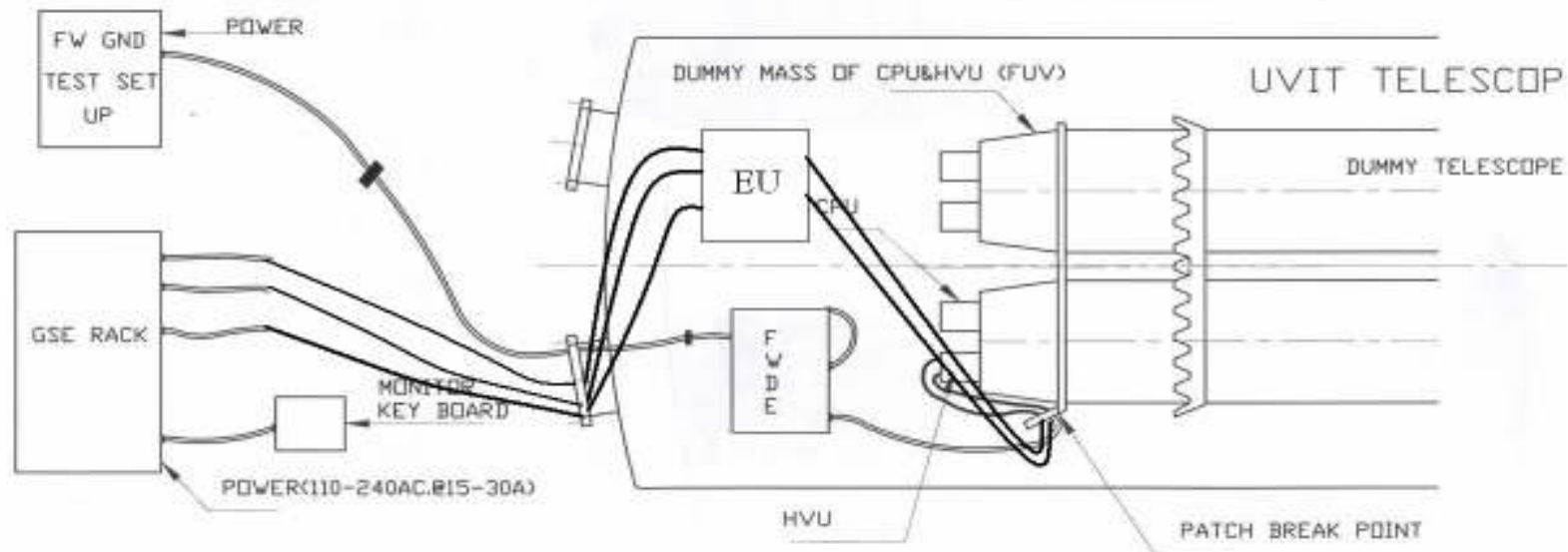
Cumulative transmission loss should be less than 2% through MgF₂ windows as measure of contamination during the period as mentioned above.

4.0 Test set up:

TEST SETUP OF ENGINEERING MODEL UVIT PAYLOAD IN TVAC AT ISAC

(ONLY ONE CHANNEL)

TVAC AT ISAC



- 1) ALL CABLES FROM CPU, HVU&FWs(ONE CHANNEL)
-WILL COME TO PATCH BREAK POINT(LENGTH ~1m.)
- 2) IN EM TELESCOPE ONE IS NUV CHANNEL, FOR VIS CHANNEL DUMMY
-MASS OF CPU,HVU&FW WILL BE MOUNTED.

Figure 4. 1 Test Setup of EM UVIT Payload in TVAC at ISITE

4.1 Mounting Fixtures

The figure 4.2 and 4.3 shows the UVIT system with the special mounting fixtures. The mounting fixtures are designed to withstand the weight of the UVIT system. The mounting fixtures are further designed to withstand the temperature environment faced in the thermo-vacuum chamber and also to ensure that it does not load the UVIT system. The UVIT system along with the mounting fixtures will be inside the thermo-vacuum chamber during the test. During the test the temperature of the thermo-vacuum shroud is monitored. The system has several temperature sensors. These will be monitored. During the test, it should be ensured that the components like detector/HVU/any other component does not exceed the operational limit specified. Adequate precautions are to be taken for proper temperature maintenance.

After the test is over the system should be immediately covered with proper cover. Also minimum electrical functional tests and mechanical checks will be carried out to ensure the system is functioning after thermo-vacuum test.

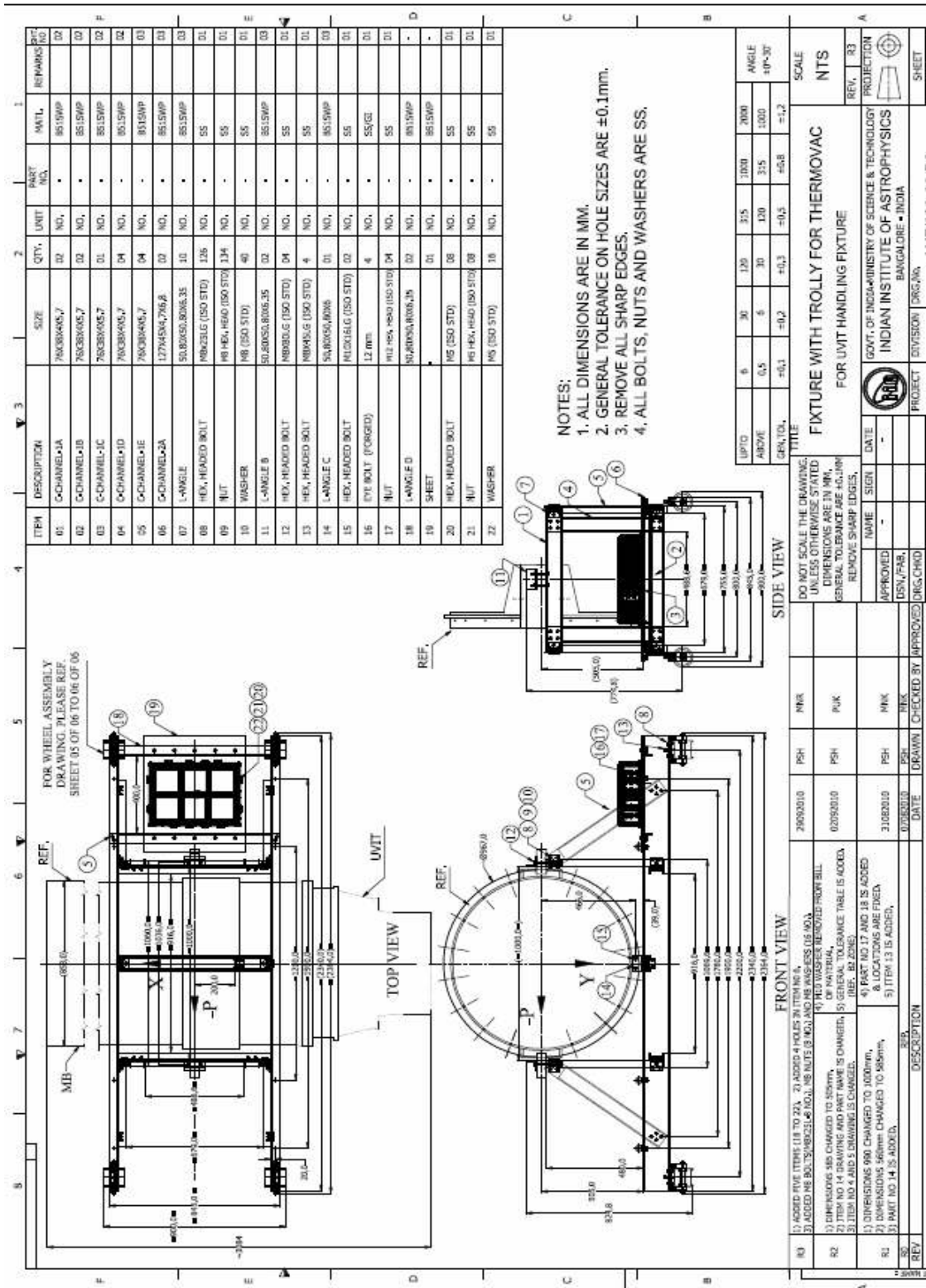


Figure 4. 2 Mounting Fixture for UVIT payload in TVAC



4.2 Instrumentation

Both, Thermal instrumentation aspects (IR Lamps, Heaters, Thermistors and Thermo couples and payload performance verification related instrumentation aspects are explained here.

4.2.1 Thermal Instrumentation:

Combination of Infra Red Lamps (mounted on IR cage) and foil heaters (bonded on the bottom surface of plate used for mounting EU and FWDE packages) are being used to realize the required temperature limits for different units of the payload system.

The temperature measurements are being done with the help of thermistors and thermocouples. The list of thermistors mounted on the payload area given in Table-E.1, given in Appendix-E. The details of the IR lamps and the temperature monitoring sensors and their locations are given in Appendix-E.

4.2.2 Payload Instrumentation

The payload performance in ambient and during Tvac tests will be performed with the help of Ground Support Equipments (GSE) developed by payload team. GSE will help in testing the detector system, Filter wheel motor with drive electronics and for monitoring the temperature at 13 locations on payload at the hot and cold plateaus during TVAC test of the UVIT payload.

For UVIT detector system, there is a dedicated system which will serve to supply Raw Power, Pulse commands, Tele-commands and receive telemetry and science data of the detector system.



Figure 4. 4 Ground Support Equipment for UVIT Detector System

For FWM and FWDE, there is a Labview based system, which will supply pulse commands and receive analog and digital telemetry of the FWM.



Figure 4. 5 Ground Support Equipment for FWM and FWDE

For Thermistors temperature monitoring also we have Labview based system, which can monitor and record the temperature of 14 thermistors at a time.

Following table 4.1 lists the location of thermistors fixed on the payload.

To supply data of thermistors from IIA system to TVAC facility system a RS232 based interface has been developed for 75 mt of cable length. The programming of RS 232 data transfer also has been done on Labview platform.

4.3 Harness Routing Plan for TVAC test

As shown in figure 4.1, the connection between EU, FWDE, thermistors and GSE will be made through ISO320 K flange using circular feed-through.

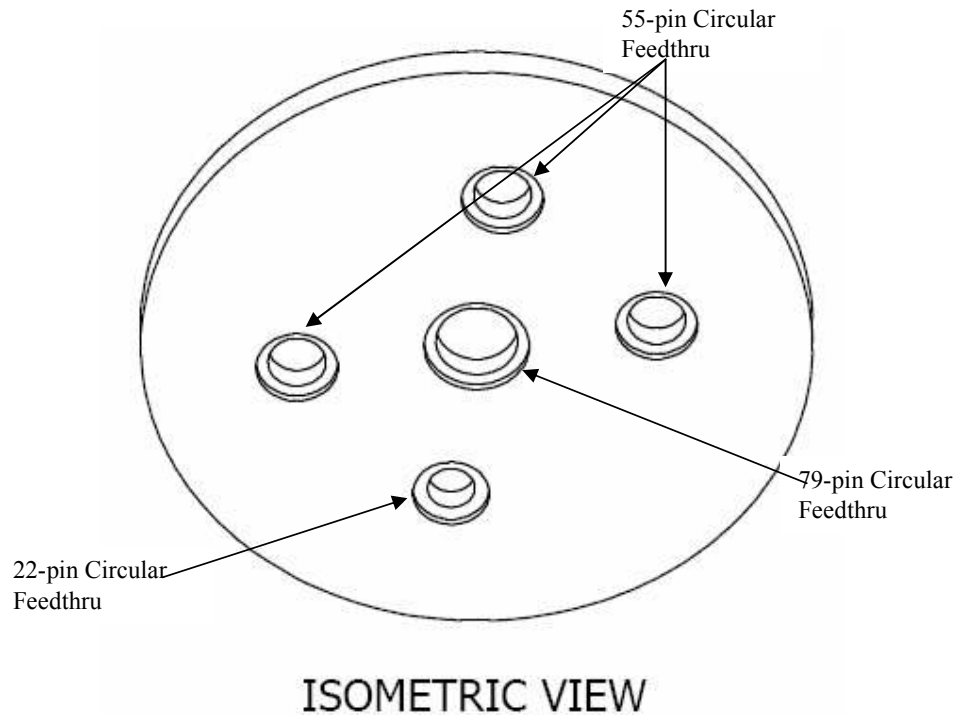


Figure 4. 6 ISO 320 K Flange

4.3.1 Grounding Requirement for UVITDS

UVITDS need to be connect a Grounding point (isolated from heavy electrical grounding point of Lab). EU box and CPU, HVU will be connected through existing EMI braid on the payload.

So we need a grounding connection till EU mounting plate from Lab isolated ground plane.

4.4 Thermal Control Implementation

To control the temperature of EM UVIT payload, thermal control hardware (i.e IR lamps, heaters and thermocouple) will be implemented by ISAC thermal group. To fix IR lamps around the payload, an IR Lamp cage has been designed and fabricated by IIA, see figure 4.7.

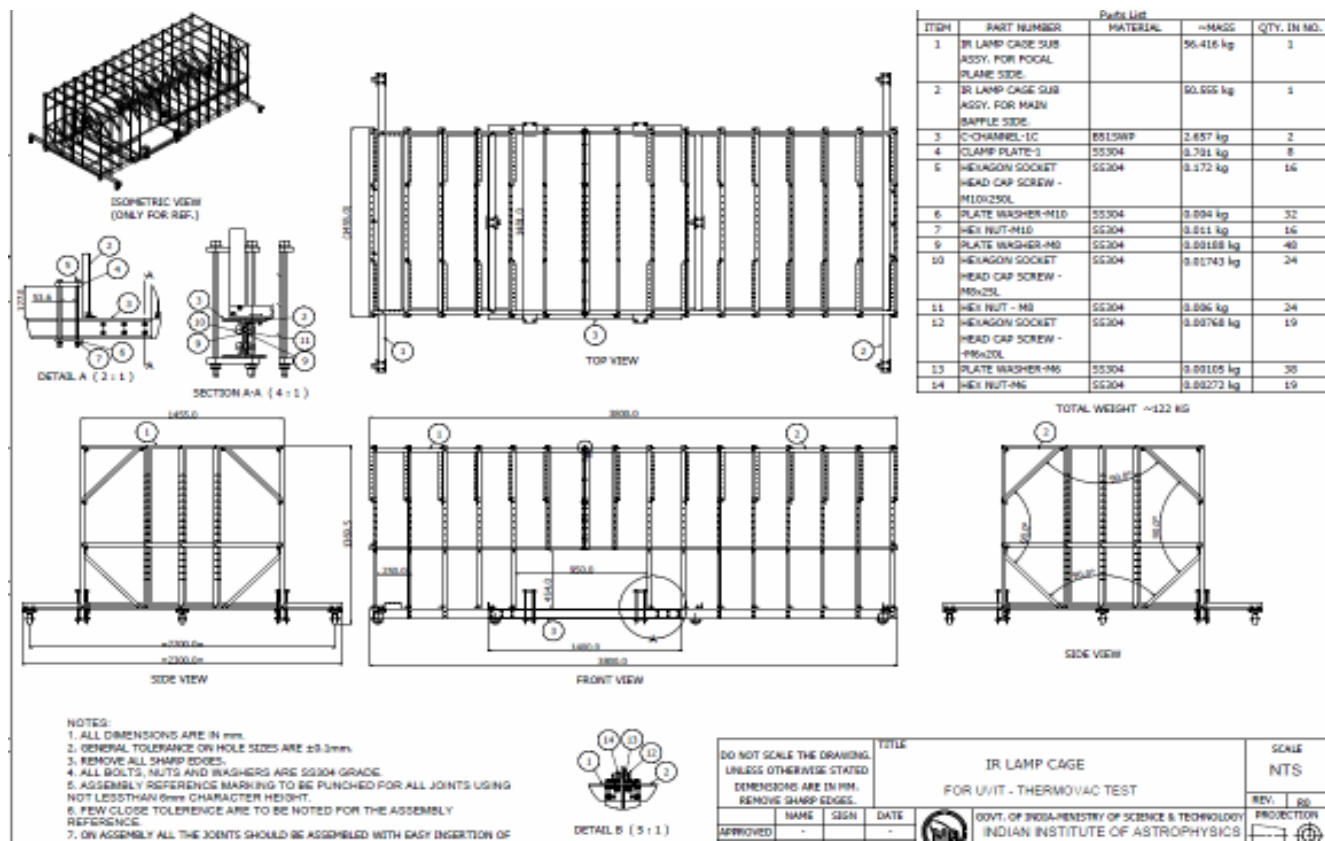


Figure 4. 7 IR Lamp cage

5. Test Results

5.1 Contamination Measurement

5.1.1 From Witness Samples

Two number of witness sample (MgF_2 window) was kept near (front and back) the payload inside TVAC chamber during the test.

Transmission loss was measured on the witness sample.

Attenuation in the transmission at 130nm-160nm band is the following:

- i) 1-1.5% during the first phase of chamber baking (without payload, with IR Lamp Cage and mounting fixture).
- ii) 2-2.5% during the TVAC test. See Table 5.1 for details.

5.1.2 From Residual Gas Analyzer (RGA)

Data is not yet received from CATVAC Facility team.

5.1.3. From TCQM

TCQM of CATVAC facility was not working properly and there is lack of data. So, no conclusion can be made, based on TCQM measurement.

Table 5. 1 Contamination Monitoring from Witness Samples (MgF₂ window)

6/5/2011 **CONTAMINATION MONITORING DURING EM-UVIT THERMO-VAC TEST AT ISITE**

Wavelength λ(nm)	W-56 Transmission Values					W-57 Transmission Values					W-06 Control Window			
	Measured on 16 March After cleaning with IPA	Measured on 12 April after exposing to TVAC chamber at ISITE	Measured on 22 April before sending back to ISITE	Measured on 06 May after exposing to TVAC chamber at ISITE		Measured on 16 March After cleaning with IPA	Measured on 12 April after exposing to TVAC chamber at ISITE	Measured on 22 April before sending back to ISITE	Measured on 06 May after exposing to TVAC chamber at ISITE		Measured on 16 March After cleaning with IPA	Measured on 12 April after exposing to TVAC chamber at ISITE	Measured on 22 April before sending back to ISITE	Measured on 06 May after exposing to TVAC chamber at ISITE
126	0.67	0.71	0.66	0.64		0.70	0.67	0.70	0.70		0.61	0.58	0.62	0.61
127	0.68	0.69	0.65	0.63		0.71	0.68	0.70	0.69		0.61	0.61	0.61	0.62
128	0.70	0.69	0.66	0.65		0.72	0.72	0.71	0.69		0.63	0.60	0.63	0.62
129	0.70	0.70	0.68	0.66		0.73	0.71	0.72	0.70		0.64	0.62	0.64	0.64
130	0.71	0.71	0.69	0.67		0.73	0.72	0.73	0.71		0.64	0.64	0.64	0.64
131	0.71	0.72	0.70	0.67		0.73	0.73	0.73	0.71		0.64	0.65	0.64	0.65
132	0.72	0.72	0.70	0.67		0.74	0.73	0.74	0.72		0.65	0.65	0.65	0.65
133	0.73	0.73	0.70	0.68		0.76	0.74	0.74	0.72		0.66	0.66	0.66	0.66
134	0.74	0.74	0.71	0.69		0.76	0.75	0.74	0.73		0.67	0.67	0.67	0.67
135	0.75	0.73	0.72	0.70		0.76	0.75	0.75	0.73		0.68	0.67	0.68	0.68
136	0.75	0.75	0.73	0.70		0.77	0.76	0.77	0.74		0.69	0.69	0.69	0.68
137	0.76	0.75	0.73	0.71		0.78	0.76	0.76	0.74		0.69	0.69	0.69	0.69
138	0.76	0.76	0.73	0.72		0.78	0.76	0.77	0.75		0.69	0.70	0.70	0.70
139	0.77	0.76	0.74	0.72		0.79	0.77	0.78	0.75		0.70	0.71	0.71	0.70
140	0.77	0.77	0.74	0.73		0.79	0.78	0.78	0.76		0.71	0.71	0.71	0.71
141	0.78	0.76	0.75	0.73		0.80	0.78	0.79	0.77		0.72	0.72	0.72	0.72
142	0.78	0.77	0.76	0.74		0.80	0.78	0.79	0.77		0.72	0.72	0.72	0.72
143	0.79	0.78	0.77	0.75		0.81	0.79	0.80	0.78		0.73	0.73	0.73	0.73
144	0.80	0.79	0.77	0.75		0.81	0.80	0.80	0.78		0.73	0.74	0.74	0.74
145	0.80	0.80	0.78	0.76		0.82	0.80	0.81	0.79		0.75	0.74	0.74	0.75
146	0.81	0.80	0.78	0.77		0.82	0.81	0.81	0.79		0.76	0.75	0.75	0.75
147	0.81	0.80	0.79	0.78		0.83	0.81	0.83	0.80		0.76	0.76	0.76	0.76
148	0.82	0.81	0.80	0.78		0.83	0.82	0.82	0.81		0.76	0.77	0.77	0.77
149	0.82	0.81	0.80	0.79		0.83	0.82	0.82	0.81		0.77	0.77	0.77	0.77
150	0.82	0.82	0.80	0.79		0.84	0.83	0.83	0.82		0.78	0.78	0.78	0.78
151	0.83	0.82	0.81	0.80		0.84	0.83	0.83	0.82		0.79	0.78	0.78	0.79
152	0.83	0.83	0.82	0.80		0.85	0.84	0.84	0.82		0.79	0.79	0.79	0.79
153	0.84	0.83	0.82	0.81		0.85	0.84	0.84	0.83		0.80	0.80	0.80	0.80

Wavelength λ (nm)	W-56 Transmission Values					W-57 Transmission Values					W-06 Control Window			
	Measured on 16 March After cleaning with IPA	Measured on 12 April after exposing to TVAC chamber at ISITE	Measured on 22 April before sending back to ISITE	Measured on 06 May after exposing to TVAC chamber at ISITE		Measured on 16 March After cleaning with IPA	Measured on 12 April after exposing to TVAC chamber at ISITE	Measured on 22 April before sending back to ISITE	Measured on 06 May after exposing to TVAC chamber at ISITE		Measured on 16 March After cleaning with IPA	Measured on 12 April after exposing to TVAC chamber at ISITE	Measured on 22 April before sending back to ISITE	Measured on 06 May after exposing to TVAC chamber at ISITE
158	0.85	0.85	0.84	0.83		0.87	0.86	0.87	0.86		0.83	0.83	0.83	0.83
159	0.86	0.85	0.84	0.83		0.87	0.86	0.87	0.85		0.83	0.83	0.83	0.83
160	0.86	0.85	0.85	0.84		0.87	0.87	0.87	0.86		0.84	0.83	0.83	0.83
161	0.86	0.86	0.85	0.84		0.88	0.87	0.87	0.86		0.84	0.84	0.84	0.84
162	0.86	0.86	0.85	0.85		0.88	0.87	0.87	0.87		0.84	0.84	0.84	0.84
163	0.87	0.86	0.85	0.85		0.88	0.87	0.86	0.87		0.85	0.84	0.84	0.84
164	0.87	0.86	0.85	0.85		0.88	0.88	0.87	0.87		0.85	0.85	0.85	0.85
165	0.87	0.86	0.86	0.85		0.88	0.88	0.88	0.87		0.85	0.85	0.85	0.85
166	0.88	0.87	0.87	0.86		0.89	0.88	0.88	0.88		0.86	0.85	0.86	0.86
167	0.88	0.87	0.87	0.86		0.89	0.88	0.89	0.88		0.86	0.86	0.86	0.86
168	0.88	0.88	0.87	0.86		0.89	0.89	0.89	0.89		0.86	0.86	0.86	0.86
169	0.88	0.88	0.88	0.87		0.89	0.89	0.89	0.89		0.86	0.86	0.86	0.86
170	0.88	0.88	0.89	0.88		0.89	0.88	0.90	0.89		0.86	0.87	0.87	0.87
171	0.88	0.88	0.89	0.88		0.90	0.89	0.90	0.89		0.87	0.86	0.87	0.87
172	0.89	0.88	0.88	0.88		0.89	0.88	0.90	0.90		0.88	0.86	0.88	0.88
173	0.88	0.89	0.89	0.88		0.90	0.90	0.91	0.90		0.87	0.86	0.87	0.87
174	0.89	0.89	0.89	0.88		0.90	0.90	0.90	0.90		0.87	0.87	0.88	0.88
175	0.89	0.89	0.89	0.88		0.90	0.90	0.90	0.90		0.87	0.87	0.89	0.89
176	0.89	0.90	0.90	0.89		0.90	0.90	0.91	0.90		0.88	0.87	0.88	0.88
177	0.89	0.90	0.90	0.89		0.90	0.90	0.91	0.90		0.88	0.88	0.89	0.89
178	0.90	0.91	0.91	0.90		0.91	0.91	0.92	0.91		0.89	0.88	0.89	0.89
179	0.90	0.90	0.90	0.89		0.91	0.90	0.91	0.91		0.89	0.88	0.89	0.89
180	0.90	0.90	0.91	0.90		0.91	0.91	0.92	0.91		0.89	0.89	0.89	0.89

5.2 Payload Performance

5.2.1 Electrical Parameters Measurement

During the test and after test, instrument (UVIT detector system and Filter Wheel Mechanism) performance was normal. Please refer figure 2.1 for temperature profile, followed during TVAC test.

Table 5. 2 Electrical Parameter Results

Name of Parameter	First Hot Cycle	First Cold Cycle	Second Hot Cycle	24 Hrs Cold Cycle	24 Hrs Hot Cycle	Post TVAC at Ambient
Performance of UVITDS (CPU, HVU and EU)	Normal	Normal	Normal	Normal	Normal	Normal
Performance of FWM & FWDE	Normal	Normal	Normal	Normal	Normal	Normal

5.2.1.1 Performance of FWM & FWDE

Performance of FWM was normal during the entire test.

Table 5. 3 Performance Details of FWM & FWDE

	Expected value in Motor Enable State	Observed value in Motor Enable State	Expected value in Motor Disable State	Observed value in Motor Disable State
Measurement Accuracy (TM-angle)	+/- 30 arc minute	+ 9.22 arc minute (max) during HOT cycle	+/- 30 arc minute	+ 11.49 arc minute (max) during HOT cycle
Motor Power Dissipation	3.5 W (max) as per specs	3.2 W (Hot cycle & amb) 3.5 W (Cold cycle)	--	--
FWDE Power Dissipation	7 W (max) as per specs	4.8 W (Hot cycle & amb) 5.44 W (Cold cycle)	--	1.6 W (Hot cycle & amb) 1.92 W (Cold cycle)

Please table 5.4 for more details.

Table 5. 4 Analog and Digital Telemetry Data for FWM & FWDE

Performance Test on FWM - FWDE at ISITE on 26/04/11 Pre TVAC in Ambient								Performance Test on FWM - FWDE at ISITE on 30/04/11 First Hot Cycle FWM at ~ +35 deg C FWDE at ~ +45 deg C					
Data Command dir/ no. of steps	Expected TM angle	Angle Telemetry				Motor Status TM		Angle Telemetry				Motor Status TM	
		Motor				Motor		Motor				Motor	
	(deg)	Enable (HEX)	Disable (HEX)	Enable (deg)	Disable (deg)	Enable (HEX)	Disable (HEX)	Enable (HEX)	Disable (HEX)	Enable (deg)	Disable (deg)	Enable (HEX)	Disable (HEX)
Safe ON cmd	x= < 1.8	104	104	1.428	1.428	34	20	F4	E0	1.3403	1.2305	34	20
CCW/ 25	x+45	20E0	20D4	46.2308	46.1649	12	0	20E0	20D0	46.2308	46.1429	12	0
CCW/ 8	x+59.4	2B34	2B34	60.7548	60.7548	12	0	2B2C	2B1C	60.7108	60.623	12	0
CCW/ 17	x+90	40F8	40F0	91.3629	91.319	11	0	40F8	40F4	91.3629	91.3409	11	0
CCW/ 17	x+120.6	56C4	56C4	122.015	122.015	18	0	56C8	56C8	122.0369	122.0369	18	0
CCW/ 8	x+135	6118	6118	136.539	136.539	18	0	6104	60F0	136.4291	136.3193	18	0
CCW/ 25	x+180	810C	8110	181.473	181.495	14	0	80FC	80F4	181.3855	181.3415	14	0
CCW/ 25	x+225	A0E8	A0D4	226.276	226.166	12	0	A0F8	A0F8	226.3638	226.3638	12	0
CCW/ 8	x+239.4	AB34	AB1C	240.756	240.624	12	0	AB40	AB3C	240.8219	240.7999	12	0
CCW/ 17	x+270	C100	C0F8	271.408	271.364	11	0	C100	C0F8	271.408	271.3641	11	0
CCW/ 17	x+300.6	D6CC	D6CC	302.06	302.06	18	0	D6C8	D6C8	302.0381	302.0381	18	0
CCW/ 8	x+315	E120	E124	316.584	316.606	18	0	E118	E118	316.5402	316.5402	18	0
CCW/25	x	F4	E8	1.34	1.274	14	0	F4	E8	1.3403	1.2744	14	0
CW/ 25	x+315	E12C	E130	316.65	316.672	38	20	E120	E120	316.5841	316.5841	38	20
CW/ 8	x+300.6	D6D8	D6D8	302.126	302.126	38	20	D6D8	D6D4	302.126	302.104	38	20
CW/ 17	x+270	C110	C10C	271.496	271.474	31	20	C110	C10C	271.4959	271.4739	31	20
CW/ 17	x+239.4	AB40	AB2C	240.822	240.712	32	20	AB4C	AB48	240.8878	240.8658	32	20
CW/ 8	x+225	A0F4	A0E4	226.342	226.254	32	20	A104	A104	226.4297	226.4297	32	20
CW/ 25	x+180	8118	811C	181.539	181.561	34	20	8108	8104	181.4514	181.4294	34	20
CW/ 25	x+135	6124	6124	136.605	136.605	38	20	6110	6100	136.495	136.4071	38	20
CW/ 8	x+120.6	56D4	56D0	122.103	122.081	38	20	56D8	56D8	122.1248	122.1248	38	20
CW/ 17	x+90	4108	4104	91.4508	91.4288	31	20	410C	4108	91.4728	91.4508	31	20
CW/ 17	x+59.4	2B48	2B44	60.8647	60.8427	32	20	2B40	2B30	60.8207	60.7328	32	20
CW/ 8	x+45	20F0	20E8	46.3187	46.2747	32	20	20E4	20D4	46.2527	46.1649	32	20
CW/ 25	x	114	118	1.516	1.5381	34	20	F8	EC	1.3623	1.2964	34	20

Analog Telemetry		After Motor Disable		After Motor Enable		After Motor Disable		After Motor Enable	
		Motor Current:		Motor Current:-1.629		Motor Current: 0.0831		Motor Current:-1.5833	
		Motor Temperature:		Motor Temperature:2.545		Motor Temperature: 1.9212		Motor Temperature:1.8535	
		DC/DC Monitoring:		DC/DC Monitoring:2.245		DC/DC Monitoring: 2.5248		DC/DC Monitoring:2.5258	
	Power ON		Power			Power ON	Power		
	Voltage (V)	Current (A)	(W)			Voltage (V)	Current (A)	(W)	
Motor Disable	32.1V	0.05 A	1.6			32	0.05	1.6	
Safe Start	32.1 V	0.15 A	4.815			32	0.15	4.8	
(Motor Enable)									

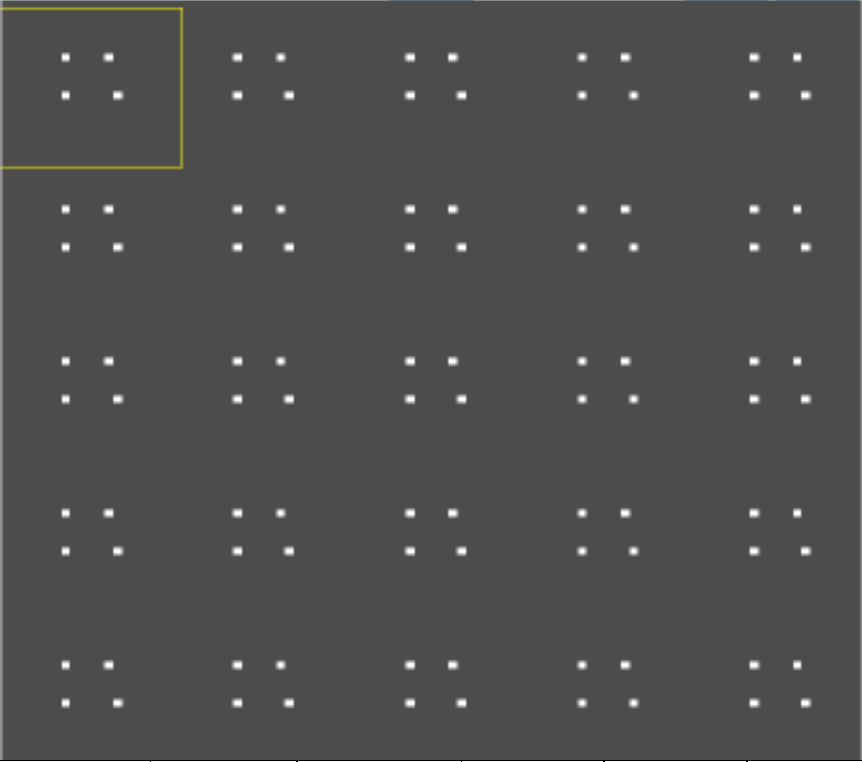
		Performance Test on FWM - FWDE at ISITE on 01/05/11 First Cold Cycle FWM at ~ -15 deg C FWDE at ~ -15 deg C						Performance Test on FWM - FWDE at ISITE on 01/05/11 Second Hot Cycle FWM at ~ +35 deg C FWDE at ~ +45 deg C					
Data Command	Expected	Angle Telemetry				Motor Status TM		Angle Telemetry				Motor Status TM	
dir/ no. of steps	TM angle	Motor				Motor		Motor				Motor	
		Enable	Disable	Enable	Disable	Enable	Disable	Enable	Disable	Enable	Disable	Enable	Disable
	(deg)	(HEX)	(HEX)	(deg)	(deg)	(HEX)	(HEX)	(HEX)	(HEX)	(deg)	(deg)	(HEX)	(HEX)
Safe ON cmdnd	x= < 1.8	F8	EC	1.3623	1.2984	34	20	F8	F4	1.3623	1.3403	34	20
CCW/ 25	x+45	20E4	20D8	46.2527	46.1888	12	0	20E4	20E0	46.2527	46.2308	12	0
CCW/ 8	x+59.4	2B2C	2B14	60.7108	60.579	12	0	2B28	2B14	60.6889	60.579	12	0
CCW/ 17	x+90	40F4	40EC	91.3409	91.297	11	0	40F8	40F4	91.3629	91.3409	11	0
CCW/ 17	x+120.6	56C4	56C4	122.015	122.015	18	0	56D4	56E0	122.1028	122.1688	18	0
CCW/ 8	x+135	6114	6114	136.517	136.517	18	0	6114	6114	136.517	136.517	18	0
CCW/ 25	x+180	80F4	80E9	181.3415	181.2756	14	0	80F4	80F0	181.3415	181.3195	14	0
CCW/ 25	x+225	A0F0	A0EC	226.3198	226.2979	12	0	A0EC	A0E8	226.2979	226.2759	12	0
CCW/ 8	x+239.4	AB3C	AB38	240.7999	240.7779	12	0	AB38	AB34	240.7779	240.756	12	0
CCW/ 17	x+270	C108	C108	271.452	271.452	11	0	C104	C100	271.43	271.408	11	0
CCW/ 17	x+300.6	D6CC	D6CC	302.0601	302.0601	18	0	D6D0	D6D0	302.0821	302.0821	18	0
CCW/8	x+315	E11C	E11C	316.5621	316.5621	18	0	E114	E110	316.5182	316.4962	18	0
CCW/25	x	F8	E8	1.3623	1.2744	14	0	E0	FF	1.2305	1.4008	14	0
CW/ 25	x+315	E128	E128	316.628	316.628	38	20	E124	E120	316.6061	316.5841	38	20
CW/ 8	x+300.6	D6D4	D6D8	302.104	302.126	38	20	D6E0	D6E0	302.1699	302.1699	38	20
CW/ 17	x+270	C114	C118	271.5179	271.5399	31	20	C118	C118	271.5399	271.5399	31	20
CW/ 17	x+239.4	AB48	AB44	240.8658	240.8439	32	20	AB4C	AB44	240.8878	240.8439	32	20
CW/ 8	x+225	A0F8	A0F8	226.3638	226.3638	32	20	A0F8	A0F4	226.3638	226.3418	32	20
CW/ 25	x+180	8100	80FC	181.4074	181.3855	34	20	8104	8104	181.4294	181.4294	34	20
CW/ 25	x+135	611C	6120	136.561	136.5829	38	20	6124	6124	136.6049	136.6049	38	20
CW/ 8	x+120.6	56CC	56CC	122.0589	122.0589	38	20	56E4	56F0	122.1907	122.2587	38	20
CW/ 17	x+90	4100	4100	91.4068	91.4068	31	20	410C	410C	91.4728	91.4728	31	20
CW/ 17	x+59.4	2B38	2B28	60.7768	60.6889	32	20	2B3C	2B3C	60.7987	60.7987	32	20
CW/ 8	x+45	20F0	20F0	46.3187	46.3187	32	20	20F4	20F0	46.3408	46.3187	32	20
CW/ 25	x	104	100	1.4282	1.4063	34	20	108	104	1.4502	1.4282	34	20
Analog Telemetry		After Motor Disable Motor Current: 0.0834 Motor Temperature: 4.0604 DC/DC Monitoring: 2.5993				After Motor Enable Motor Current:-1.8139 Motor Temperature:3.9715 DC/DC Monitoring:2.5922		After Motor Disable Motor Current: 0.0818 Motor Temperature: 1.6780 DC/DC Monitoring: 2.5232				After Motor Enable Motor Current:-1.5469 Motor Temperature:1.6309 DC/DC Monitoring:2.5226	
		Power ON		Power				Power ON		Power			
		Voltage (V)	Current (A)		(W)			Voltage (V)	Current (A)		(W)		
Motor Disable		32	0.06		1.92			32	0.05		1.6		
Safe Start		32	0.17		5.44			32	0.15		4.8		
(Motor Enable)													

		Long Cold Cycle						Long Hot Cycle					
		FWM at ~ -15 deg C FWDE at ~ -15 deg C						FWM at ~ +35 deg C FWDE at ~ +45 deg C					
Data Command dir/ no. of steps	Expected TM angle	Angle Telemetry				Motor Status TM		Angle Telemetry				Motor Status TM	
		Motor				Motor		Motor				Motor	
		Enable (HEX)	Disable (HEX)	Enable (deg)	Disable (deg)	Enable (HEX)	Disable (HEX)	Enable (HEX)	Disable (HEX)	Enable (deg)	Disable (deg)	Enable (HEX)	Disable (HEX)
Safe ON cmd	x= < 1.8	E8	B8	1.2744	1.0107	34	20	E0	C0	1.2305	1.0547	34	20
CCW/ 25	x+45	20E4	20E0	46.2527	46.2308	12	0	20E0	20E0	46.2308	46.2308	12	0
CCW/ 8	x+59.4	2B28	2B18	60.6889	60.601	12	0	2B24	2B14	60.6889	60.579	12	0
CCW/ 17	x+90	40F8	40F0	91.3629	91.319	11	0	40F8	40F8	91.3629	91.3629	11	0
CCW/ 17	x+120.6	56C0	56BC	121.993	121.971	18	0	56C0	56C0	121.993	121.993	18	0
CCW/ 8	x+135	6110	610C	136.495	136.4731	18	0	610C	6108	136.4731	136.4511	18	0
CCW/ 25	x+180	80FC	80F8	181.3855	181.3635	14	0	80F8	80F4	181.3635	181.3415	14	0
CCW/ 25	x+225	A0EC	A0E4	226.2979	226.2539	12	0	A0EC	A0E8	226.2979	226.2759	12	0
CCW/ 8	x+239.4	AB40	AB3C	240.8219	240.7999	12	0	AB40	AB3C	240.8219	240.7999	12	0
CCW/ 17	x+270	C100	C0F8	271.408	271.3641	11	0	C104	C100	271.43	271.408	11	0
CCW/ 17	x+300.6	D6C8	D6C8	302.0381	302.0381	18	0	D6D0	D6D0	302.0821	302.0821	18	0
CCW/8	x+315	E118	E118	316.5402	316.5402	18	0	E118	E118	316.5402	316.5402	18	0
CCW/25	x	F4	E4	1.3403	1.2524	14	0	F0	E0	1.3184	1.2305	14	0
CW/ 25	x+315	E128	E128	316.628	316.628	38	20	E128	E128	316.628	316.628	38	20
CW/ 8	x+300.6	D6CC	D6CC	302.0601	302.0601	38	20	D6E0	D6E0	302.1699	302.1699	38	20
CW/ 17	x+270	C10C	C10C	271.4739	271.4739	31	20	C118	C118	271.5399	271.5399	31	20
CW/ 17	x+239.4	AB4C	AB4C	240.8878	240.8878	32	20	AB50	AB4C	240.9098	240.8878	32	20
CW/ 8	x+225	A0F4	A0F0	226.3418	226.3198	32	20	A0F8	A0F4	226.3638	226.3418	32	20
CW/ 25	x+180	8108	8108	181.4514	181.4514	34	20	8108	8108	181.4514	181.4514	34	20
CW/ 25	x+135	6118	6118	136.539	136.539	38	20	611C	6118	136.561	136.539	38	20
CW/ 8	x+120.6	56C8	56C8	122.0369	122.0369	38	20	56D0	56D0	122.0809	122.0809	38	20
CW/ 17	x+90	4104	4104	91.4288	91.4288	31	20	410C	410C	91.4728	91.4728	31	20
CW/ 17	x+59.4	2B38	2B2C	60.7768	60.7108	32	20	2B3C	2B30	60.7987	60.7328	32	20
CW/ 8	x+45	20F4	20F4	46.3406	46.3406	32	20	20F8	20F8	46.3626	46.3626	32	20
CW/ 25	x	F4	FF	1.3403	1.4008	34	20	F4	DC	1.3403	1.2085	34	20
Analog Telemetry		After Motor Disable Motor Current: 0.0863 Motor Temperature: 4.0746 DC/DC Monitoring: 2.5915				After Motor Enable Motor Current:-1.8767 Motor Temperature:4.0047 DC/DC Monitoring:2.5941		After Motor Disable Motor Current: 0.0802 Motor Temperature: 1.7817 DC/DC Monitoring: 2.5248				After Motor Enable Motor Current:-1.5765 Motor Temperature:1.7256 DC/DC Monitoring:2.5226	
		Power ON		Power				Power ON		Power			
		Voltage (V)		Current (A)	(W)			Voltage (V)		Current (A)	(W)		
Motor Disable		32		0.05	1.6			32		0.05	1.6		
Safe Start		32		0.17	5.44			32		0.15	4.8		
(Motor Enable)													

5.2.1.2 Performance of UVITDS (CPU, HVU & EU)

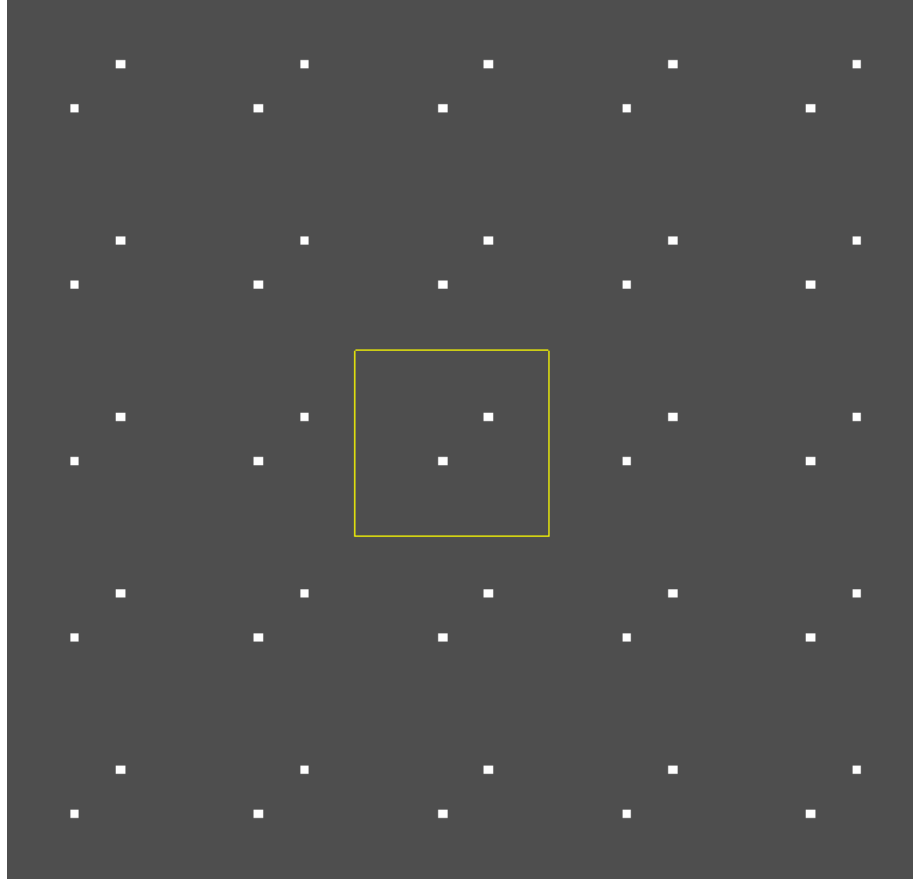
Following are parameters observed during the test and performance of UVITDS was normal.

Table 5. 5 Measurement of UVITDS-Parameters

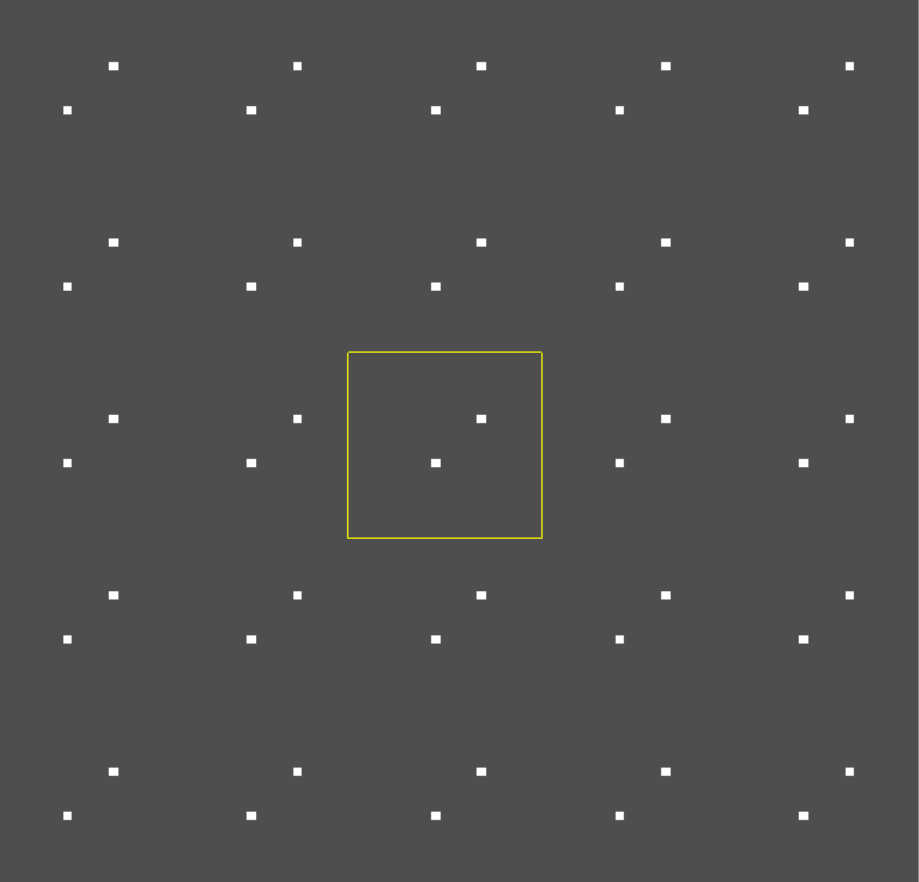
Pass Fail Criteria		First Hot Cycle	First Cold Cycle	Second Hot Cycle	24 Hrs Cold Cycle	24 Hrs Hot Cycle	Post TVAC at Ambient
Name of Parameter	Expected Value	Observed Value	Observed Value	Observed Value	Observed Value	Observed Value	Observed Value
Std. Deviation	< 30	6.59 (6.37;Pre-Tvac)	5.61	7.87	5.61	6.94	6.49
A-elec100 Pattern-cent10-4events-EE (stored pattern, Photon counting mode)							
							
Total No. of events	100	100(100Pre-Tvac)	100	100	100	100	100
Window Size	100x 100	100x 100	100x 100	100x 100	100x 100	100x 100	100x 100
Total num of pixels	10000	10000	10000	10000	10000	10000	10000
Num of Bright Pixels	100	100	100	100	100	100	100
Num of dark Pixels	9900	9900	9900	9900	9900	9900	9900

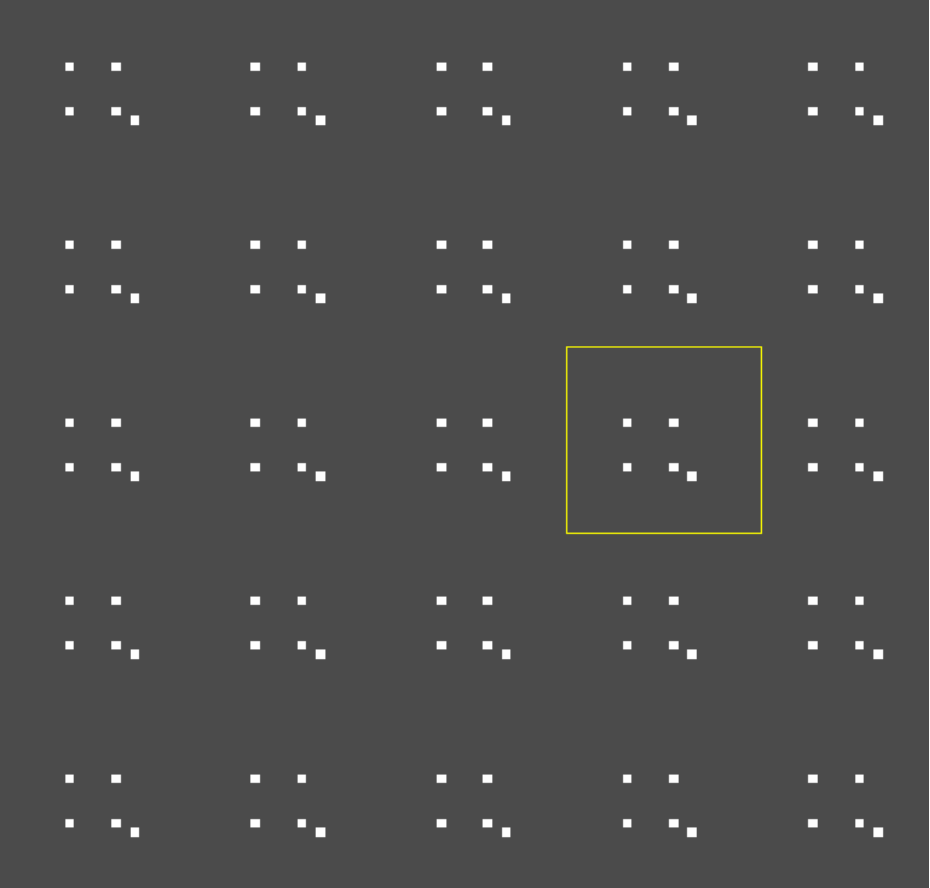
		First Hot Cycle	First Cold Cycle	Second Hot Cycle	24 Hrs Cold Cycle	24 Hrs Hot Cycle	Post TVAC at Ambient
Name of Parameter	Expected Value	Observed Value	Observed Value	Observed Value	Observed Value	Observed Value	Observed Value
Event Grouping	4	4	4	4	4	4	4
X-Y Coordinates	No shift	Pass	Pass	Pass	Pass	Pass	Pass

B-elec100-pattern-cent10-2events-EE (stored Pattern, Photon counting mode)



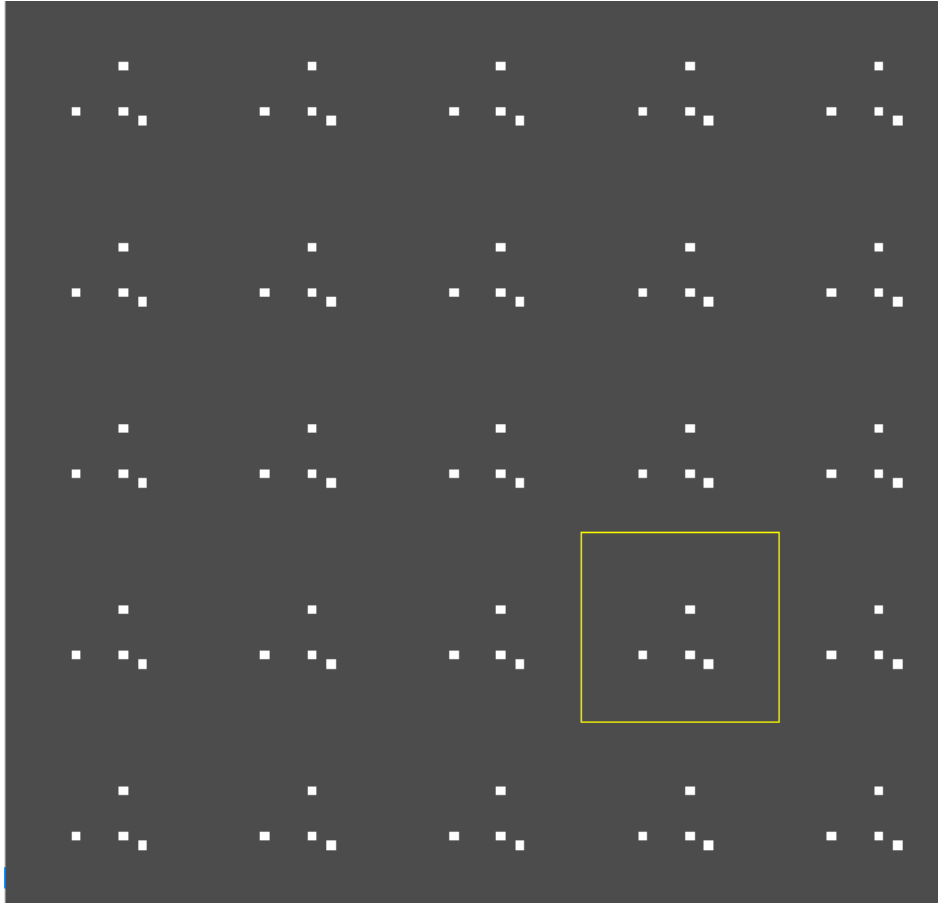
Total No. of events	50	50	50	50	50	50	50
Window Size	100x 100	100x 100	100x 100	100x 100	100x 100	100x 100	100x 100
Total num of pixels	10000	10000	10000	10000	10000	10000	10000
Num of Bright pixels	50	50	50	50	50	50	50
Num of dark Pixels	9950	9950	9950	9950	9950	9950	9950
Event Grouping	2	2	2	2	2	2	2
X-Y Coordinates	No Shift	Pass	Pass	Pass	Pass	Pass	Pass

		First Hot Cycle	First Cold Cycle	Second Hot Cycle	24 Hrs Cold Cycle	24 Hrs Hot Cycle	Post TVAC at Ambient
Name of Parameter	Expected Value	Observed Value	Observed Value	Observed Value	Observed Value	Observed Value	Observed Value
C-elec100-pattern-cent10-2events-EE (Stored Pattern, Photon counting mode)							
							
Total No. of events	50	50	50	50	50	50	50
Window Size	100x 100	100x 100	100x 100	100x 100	100x 100	100x 100	100x 100
Total num of pixels	10000	10000	10000	10000	10000	10000	10000
Num of Bright pixels	50	50	50	50	50	50	50
Num of dark Pixels	9950	9950	9950	9950	9950	9950	9950
Event Grouping	2	2	2	2	2	2	2
X-Y Cordinates	No Shift	Pass	Pass	Pass	Pass	Pass	Pass

		First Hot Cycle	First Cold Cycle	Second Hot Cycle	24 Hrs Cold Cycle	24 Hrs Hot Cycle	Post TVAC at Ambient
Name of Parameter	Expected Value	Observed Value	Observed Value	Observed Value	Observed Value	Observed Value	Observed Value
P-elec100-pattern-cent01-5events-EE (stored pattern, Photon counting mode)							
							
Total No. of events	125	125	125	125	125	125	125
Window Size	100x 100	100x 100	100x 100	100x 100	100x 100	100x 100	100x 100
Total num of pixels	10000	10000	10000	10000	10000	10000	10000
Num of Bright pixels	125	125	125	125	125	125	125
Num of dark Pixels	9875	9875	9875	9875	9875	9875	9875
Event Grouping	5	5	5	5	5	5	5
X-Y Coordinates	No Shift	Pass	Pass	Pass	Pass	Pass	Pass

		First Hot Cycle	First Cold Cycle	Second Hot Cycle	24 Hrs Cold Cycle	24 Hrs Hot Cycle	Post TVAC at Ambient
Name of Parameter	Expected Value	Observed Value	Observed Value	Observed Value	Observed Value	Observed Value	Observed Value

Q-elec100-pattern-cent00-4events-EE (Stored Pattern, Photon counting mode)



Total No. of events	100	100	100	100	100	100	100
Window Size	100x 100	100x 100	100x 100	100x 100	100x 100	100x 100	100x 100
Total num of pixels	10000	10000	10000	10000	10000	10000	10000
Num of Bright pixels	100	100	100	100	100	100	100
Num of dark Pixels	9900	9900	9900	9900	9900	9900	9900
Event Grouping	4	4	4	4	4	4	4
X-Y Cordinates	No Shift	Pass	Pass	Pass	Pass	Pass	Pass

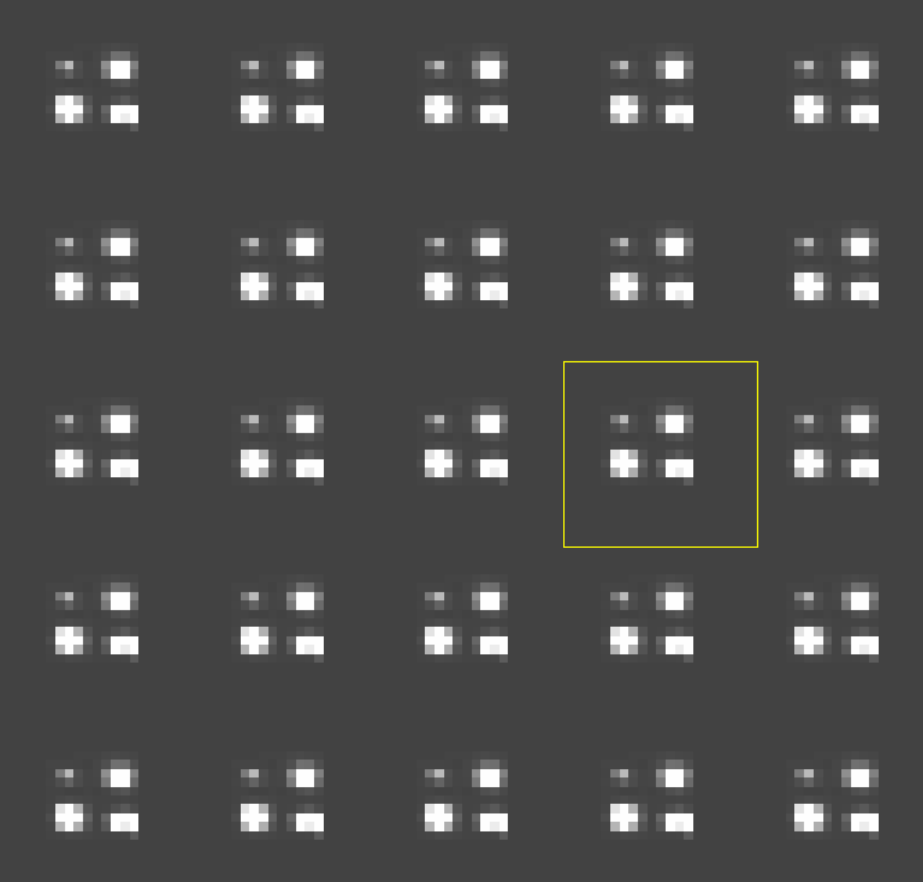
		First Hot Cycle	First Cold Cycle	Second Hot Cycle	24 Hrs Cold Cycle	24 Hrs Hot Cycle	Post TVAC at Ambient
Name of Parameter	Expected Value	Observed Value	Observed Value	Observed Value	Observed Value	Observed Value	Observed Value
N-elec100-Pattern_int (Single Frame, Integration Mode)							
							
Window Size	100x 100	100x 100	100x 100	100x 100	100x 100	100x 100	100x 100
Event Grouping	4	4	4	4	4	4	4
X-Y Coordinates	No shift	Pass	Pass	Pass	Pass	Pass	Pass
Power Dissipation (W) at 36V (35.9V actual) [For One channel only]							
Low Power Mode	9 (+/-10%)	8.257 (8.257; Pre)	9.334	8.257	9.334	8.616	8.257
Stand-By Mode & Active Mode	18 (+/-10%)	18.309 (17.591; Pre-Tvac)	17.591	17.95	17.591	18.668	17.95
All Digital Telemetry (Voltages & current)	Normal (as per nominal value given)	Normal (Normal; Pre-Tvac)	Normal	Normal	Normal	Normal	Normal

Table 5. 6 Digital Telemetry Data of EM-UVITDS (NUV Channel) During Long Cold Cycle

Telemetry Parameters of EM-UVITDS to be Monitored During TVAC 24 hrs Cold Cycle (-15 deg C)										Every 30 mins
Warning: Please maintain Temp -15deg C +2/-0										
	Date	2/5/11	2/5/11							
	Time	12:45 PM	1:15 PM	1:45 PM	2:25 PM	2:55 PM	3:40 PM	4:10 PM	4:40 PM	5:10 PM
	Expected Values				-13.8					
Name of Parameter										
CPU Temp (From 2nd Rack Monitor)	(-15 deg C) Max	-13.6	-13.1		-15.5		-13.5			
EU Plate Thermocouple Temp (from Thermal group) <i>Call 52.68</i>	(-15 deg C) Max			-15.5	-15.5				-15.50	-16
Detector State	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By
REA +5 V	~ +5V (+/- 10%)	4.90	4.90	4.90	4.90	4.90	4.91	4.90	4.90	4.91
REA +3.3 V	~ +3.3V (+/- 10%)	3.25	3.25	3.25	3.25	3.25	3.25	3.25	3.25	3.25
REA +12 V	~ +12V (+/- 10%)	11.86	11.86	11.84	11.84	11.84	11.84	11.86	11.86	11.86
REA -12 V	~ -12V (+/- 10%)	-11.89	-11.88	-11.86	-11.89	-11.89	-11.86	-11.88	-11.86	-11.86
REA +5V Current (A)	Fill as actuals	3.02	2.98	2.97	2.97	3.0	2.98	2.97	3.05	2.97
REA +12V Current (A)	Fill as actuals	0.07	0.07	0.07	0.07	0.07	0.07	0.07	0.07	0.07
REA -12V Current (A)	Fill as actuals	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03
REA +3V Current (A)	Fill as actuals	0.83	0.82	0.82	0.84	0.90	0.83	0.82	0.81	0.83
REA FPGA Temp	Fill as actuals	-1.02	-1.17	0.29	0.05	-0.28	-0.62	-0.73	-1.30	-1.57
REA DC/DC Temp	Fill as actuals	0.88	1.66	1.98	1.75	1.39	1.15	0.99	0.29	0.27
REA Oscillator Temp	Fill as actuals	1.79	2.24	2.63	2.45	2.18	1.81	1.70	1.10	0.89
CPU +12 V	~ +12V (+/- 10%)	11.83	11.81	11.81	11.80	11.80	11.81	11.83	11.83	11.83
CPU -12 V	~ -12V (+/- 10%)	-11.81	-11.89	-11.91	-11.89	-11.89	-0.03	-11.89	-11.91	-11.91
CPU +12V Current	Fill as actuals	0.10	0.10	0.10	0.10	0.10	0.00	0.10	0.10	0.10
CPU -12V Current	Fill as actuals	-0.05	-0.05	-0.05	-0.05	-0.05	-0.00	-0.05	-0.05	-0.05
STAR 250 temp	Fill as actuals	-11.13	-10.57	-11.66	-11.73	-11.80	-11.37	-11.66	-12.45	-12.60
HVU +15 V	~ +15V (+/- 10%)	14.72	14.76	14.76	14.76	14.76	14.76	14.77	14.76	14.76
HVU +30V	~ +21V (+/- 10%)	22.49	22.76	22.95	22.86	22.78	22.65	22.60	22.39	22.34
HVU -15V	~ -15V (+/- 10%)	-15.37	-15.35	-15.37	-15.37	-15.34	-15.35	-15.35	-15.37	-15.37
HVU +30 V Current	Fill as actuals	0.04	0.04	0.03	0.03	0.03	0.03	0.03	0.04	0.03
HVU +15 V Current	Fill as actuals	0.09	0.09	0.09	0.09	0.09	0.09	0.09	0.09	0.09
HVU -15 V Current	Fill as actuals	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01
HVU Anode Voltage	less than 25 V	11.59	11.59	11.59	11.7	11.59	11.59	11.59	11.59	11.59
HVU MCP Voltage	less than 10V	7.81	7.81	3.10	7.81	0.02	7.81	3.10	7.81	3.10
HVU Cathode Voltage	positive voltage (less than 60V)	55.61	55.14	55.61	55.61	55.63	55.61	55.61	55.61	55.61
HVU Temp	Fill as actuals	6.38	6.38	6.31	6.53	6.44	6.99	6.92	6.56	6.36

Telemetry Parameters of EM-UVITDS to be Monitored During TVAC 24 hrs Cold Cycle (-15 deg C)

Every 30 mins

Warning: Please maintain Temp -15deg C +2/-0		(-13 deg C to -15 deg C)							
	Date	2/5/11	2/5/11	2/5/11	2/5/11	2/5/11			
	Time	05:40pm	06:10pm	06:40pm	7:10pm	7:40			
Name of Parameter	Expected Values								
CPU Temp (From 2nd Rack Monitor)	(-15 deg C) Max	-14.6	-14.3	-14.5	-14.3				
EU Plate Thermocouple Temp (from Thermal group) <i>Call 5268</i>	(-15 deg C) Max	-15 to -16			-15 to -16				
Detector State	Stand By	standby	standby	standby	standby	standby			
REA +5 V	~ +5V (+/- 10%)	4.92	4.90	4.90	4.90	4.90			
REA +3.3 V	~ +3.3V (+/- 10%)	3.25	3.25	3.25	3.25	3.25			
REA +12 V	~ +12V (+/- 10%)	11.86	11.86	11.86	11.86	11.86			
REA -12 V	~ -12V (+/- 10%)	-11.86	-11.86	-11.84	-11.84	-11.86			
REA +5V Current (A)	Fill as actuals	3.02	3.02	3.02	3.0	3.02			
REA +12V Current (A)	Fill as actuals	0.06	0.06	0.06	0.06	0.06			
REA -12V Current (A)	Fill as actuals	-0.03	-0.03	-0.03	-0.03	-0.03			
REA +3V Current (A)	Fill as actuals	0.79	0.83	0.84	0.83	0.83			
REA FPGA Temp	Fill as actuals	-1.41	-1.13	-1.07	-0.94	-1.81			
REA DC/DC Temp	Fill as actuals	0.44	0.72	0.88	0.83	-0.16			
REA Oscillator Temp	Fill as actuals	1.10	1.37	1.50	1.44	0.66			
CPU +12 V	~ +12V (+/- 10%)	11.81	11.81	11.81	11.81	11.80			
CPU -12 V	~ -12V (+/- 10%)	-11.89	-11.89	-11.89	-11.91	-11.89			
CPU +12V Current	Fill as actuals	0.10	0.10	0.10	0.10	0.10			
CPU -12V Current	Fill as actuals	-0.05	-0.05	-0.05	-0.05	-0.05			
STAR 250 temp	Fill as actuals	-12.24	-12.30	-12.02	-12.01	-11.98			
HVU +15 V	~ +15V (+/- 10%)	14.76	14.76	14.76	14.74	14.76			
HVU +30V	~ +21V (+/- 10%)	22.37	22.47	22.54	22.55	22.23			
HVU -15V	~ -15V (+/- 10%)	-15.35	-15.35	-15.35	-15.37	-15.35			
HVU +30 V Current	Fill as actuals	0.03	0.03	0.03	0.03	0.03			
HVU +15 V Current	Fill as actuals	0.09	0.09	0.09	0.09	0.09			
HVU -15 V Current	Fill as actuals	-0.01	-0.01	-0.01	-0.01	-0.01			
HVU Anode Voltage	less than 25 V	11.59	11.59	11.59	11.59	11.59			
HVU MCP Voltage	less than 10V	7.81	7.81	7.81	7.81	7.81			
HVU Cathode Voltage	positive voltage (less than 60V)	55.61	55.61	55.61	55.61	56.08			
HVU Temp	Fill as actuals	6.16	6.41	6.38	6.73	6.70			

Table 5. 7 Digital Telemetry Data of EM-UVITDS (NUV Channel) During Long Hot Cycle

Telemetry Parameters of EM-UVITDS to be Monitored During TVAC 24 hrs Hot Cycle (+35 deg C +0/-2 deg C)										Every 30 Mins
Warning: Please maintain Temp CPU, HVU (+35 deg C) & EU (+45 deg C)										
Date	3/5/11									
Time	9:00AM	10:AM	10:30	11:00AM	11:30AM	12:00	12:45	1-15PM	1-45PM	
Name of Parameter	Expected Values									
CPU Temp (From 2nd Rack Monitor)	(+35 deg C) Max	34.5°C	29.9°C	30.7	32.5	33.5	23.8	34.5°	34.7°	34.9°
EU Plate Thermocouple Temp (from Thermal group) call 5268	(+45 deg C) Max	41.5°C	41.5°C	41.0°C	41°C	45.5°C	45.5°C	40.4		
Detector State	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By
REA +5 V	~ +5V (+/- 10%)	4.91	4.91	4.91	4.88	4.88	4.88	4.92	4.89	4.88
REA +3.3 V	~ +3.3V (+/- 10%)	3.23	3.22	3.24	3.23	3.23	3.23	3.23	3.23	3.23
REA +12 V	~ +12V (+/- 10%)	11.84	11.86	11.86	11.84	11.84	11.86	11.84	11.84	11.84
REA -12 V	~ -12V (+/- 10%)	-11.84	-11.88	-11.86	-11.83	-11.81	-11.83	-11.88	-11.86	-11.83
REA +5V Current (A)	Fill as actuals	3.43	3.75	3.53	3.53	3.38	3.54	3.48	3.52	3.17
REA +12V Current (A)	Fill as actuals	0.06	0.06	0.06	0.05	0.05	0.05	0.07	0.06	0.05
REA -12V Current (A)	Fill as actuals	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03
REA +3V Current (A)	Fill as actuals	1.03	1.26	1.05	1.08	1.06	1.05	1.06	1.07	1.06
REA FPGA Temp	Fill as actuals	54.26	58.09	58.84	59.62	59.87	60.37	59.17	60.20	59.86
REA DC/DC Temp	Fill as actuals	58.19	61.52	62.60	63.53	63.81	64.12	61.89	63.91	63.72
REA Oscillator Temp	Fill as actuals	56.72	60.48	61.25	62.24	62.53	62.80	61.34	62.62	62.51
CPU +12 V	~ +12V (+/- 10%)	11.80	11.80	11.78	11.78	11.80	11.78	11.78	11.80	11.80
CPU -12 V	~ -12V (+/- 10%)	-11.89	-11.91	-11.91	-11.89	-11.91	-11.91	-11.89	-11.89	-11.91
CPU +12V Current	Fill as actuals	0.10	0.10	0.10	0.10	0.10	0.10	0.10	0.10	0.10
CPU -12V Current	Fill as actuals	-0.05	-0.05	-0.05	-0.05	-0.05	-0.05	-0.05	-0.05	-0.05
STAR 250 temp	Fill as actuals	35.92	30.30	32.09	34.17	34.77	36.65	35.49	36.36	38.57
HVU +15 V	~ +15V (+/- 10%)	14.74	14.74	14.73	14.73	14.74	14.73	14.79	14.73	14.74
HVU +30V	~ +30V (+/- 10%)	29.83	29.83	29.83	29.83	29.83	29.83	29.84	29.83	29.83
HVU -15V	~ -15V (+/- 10%)	-15.37	-15.35	-15.37	-15.37	-15.37	-15.37	-15.39	-15.37	-15.37
HVU +30 V Current	Fill as actuals	0.03	0.03	0.03	0.03	0.03	0.03	0.03	0.03	0.03
HVU +15 V Current	Fill as actuals	0.11	0.11	0.11	0.11	0.11	0.11	0.11	0.11	0.11
HVU -15 V Current	Fill as actuals	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01
HVU Anode Voltage	less than 25 V	11.59	11.59	11.59	11.59	11.59	11.59	11.59	11.59	11.59
HVU MCP Voltage	less than 10V	7.10	7.81	7.81	7.81	7.81	7.81	7.81	7.81	7.81
HVU Cathode Voltage	positive voltage (less than 60V)	55.61	55.61	56.08	56.08	56.08	56.08	55.61	55.61	55.61
HVU Temp	Fill as actuals	49.52	51.11	51.63	53.05	53.36	54.26	49.43	54.85	55.38

Telemetry Parameters of EM-UVITDS to be Monitored During TVAC 24 hrs Hot Cycle (+35 deg C +0/-2 deg C) Every 30 Mins

Warning: Please maintain Temp CPU, HVU (+35 deg C) & EU (+45 deg C)												
Date	3/5/11							3/5/11			3/5/11	3/5/11
Time	9-15 Pm	2-45 Pm	3-15 Pm	3-45 Pm	4-15 Pm	4-45 Pm	5-25 Pm	6-00 Pm	6-30 Pm	7-00 Pm	7-30 Pm	
Name of Parameter	Expected Values											
CPU Temp (From 2nd Rack Monitor)	(+35 deg C) Max	35.02°	34.7°	34.2°	34.1°	33.3°	32.8°	32.6°	31.7°	31.36°	31.1°	30.8°c
EU Plate Thermocouple Temp (from Thermal group) call 5268	(+45 deg C) Max		44.4		44.3			44.2			38.67°	
Detector State	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By
REA +5 V	~ +5V (+/- 10%)	4.88	4.92	4.87	4.87	4.92	4.87	4.87	4.87	4.88	4.87	4.88
REA +3.3 V	~ +3.3V (+/- 10%)	3.23	3.24	3.23	3.23	3.23	3.23	3.23	3.23	3.23	3.24	3.23
REA +12 V	~ +12V (+/- 10%)	11.86	11.86	11.86	11.84	11.84	11.84	11.84	11.84	11.86	11.86	11.86
REA -12 V	~ -12V (+/- 10%)	-11.83	-11.81	-11.81	-11.83	-11.83	-11.83	-11.83	-11.83	-11.83	-11.81	-11.81
REA +5V Current (A)	Fill as actuals	3.53	3.49	3.52	3.59	3.24	3.46	3.31	3.41	3.22	3.4	3.49
REA +12V Current (A)	Fill as actuals	0.05	0.05	0.05	0.05	0.05	0.05	0.05	0.05	0.05	0.05	0.05
REA -12V Current (A)	Fill as actuals	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03
REA +3V Current (A)	Fill as actuals	1.04	1.08	1.09	1.06	1.06	1.02	1.07	1.06	1.08	1.10	1.05
REA FPGA Temp	Fill as actuals	59.70	59.62	59.53	59.60	59.45	59.43	59.36	59.36	59.34	59.34	59.36
REA DC/DC Temp	Fill as actuals	63.61	63.46	63.36	63.27	63.36	63.27	63.27	63.18	63.25	63.25	63.18
REA Oscillator Temp	Fill as actuals	62.33	62.24	62.08	62.15	61.99	61.89	61.89	61.89	61.89	61.97	61.80
CPU +12 V	~ +12V (+/- 10%)	11.78	11.78	11.76	11.78	11.80	11.87	11.80	11.78	11.78	11.80	11.78
CPU -12 V	~ -12V (+/- 10%)	-11.89	-11.89	-11.91	-11.89	-11.89	-11.89	-11.91	-11.89	-11.91	-11.89	-11.89
CPU +12V Current	Fill as actuals	0.10	0.10	0.10	0.10	0.10	0.10	0.10	0.10	0.10	0.10	0.10
CPU -12V Current	Fill as actuals	-0.05	-0.05	-0.05	-0.05	-0.05	-0.05	-0.05	-0.05	-0.05	-0.05	-0.05
STAR 250 temp	Fill as actuals	36.54	36.21	35.82	35.53	34.75	34.19	33.98	32.99	32.62	32.34	32.19
HVU +15 V	~ +15V (+/- 10%)	14.73	14.74	14.74	14.74	14.73	14.74	14.74	14.73	14.73	14.74	14.73
HVU +30V	~ +30V (+/- 10%)	29.24	29.24	29.24	29.24	29.24	29.83	29.83	29.83	29.84	29.83	29.84
HVU -15V	~ -15V (+/- 10%)	-15.37	-15.37	-15.37	-15.37	-15.37	-15.37	-15.37	-15.37	-15.37	-15.37	-15.37
HVU +30 V Current	Fill as actuals	0.03	0.03	0.03	0.03	0.03	0.03	0.03	0.03	0.03	0.03	0.03
HVU +15 V Current	Fill as actuals	0.11	0.11	0.11	0.11	0.11	0.11	0.11	0.11	0.11	0.11	0.11
HVU -15 V Current	Fill as actuals	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01
HVU Anode Voltage	less than 25 V	11.01	11.59	11.59	11.59	11.59	11.59	11.59	11.59	11.59	11.59	11.59
HVU MCP Voltage	less than 10V	7.81	7.81	7.81	7.81	7.81	7.81	7.81	7.81	7.81	7.81	7.81
HVU Cathode Voltage	positive voltage (less than 60V)	55.61	55.61	55.61	55.61	55.61	56.08	55.61	55.61	55.61	55.61	56.08
HVU Temp	Fill as actuals	55.48	55.38	55.38	54.94	54.62	54.03	54.09	53.20	52.90	52.49	52.40

Telemetry Parameters of EM-UVITDS to be Monitored During TVAC 24 hrs Hot Cycle (+35 deg C +0/-2 deg C)

Every 30 Mins

Warning: Please maintain Temp CPU, HVU (+35 deg C) & EU (+45 deg C)

	Date	3/5/11								
	Time	8:00pm	8:30pm	9:00pm	9:30pm	10:00pm	10:30pm	11:00pm	11:30pm	12:00am
Name of Parameter	Expected Values	8								
CPU Temp (From 2nd Rack Monitor)	(+35 deg C) Max	30.6°	30.8	31.0	31.2	31.3	31.4	31.2	31.4	31.4
EU Plate Thermocouple Temp (from Thermal group) call 5268	(+45 deg C) Max		38 to 40	38 to 40	38 to 40	38 to 40	38 to 40	38 to 40	37 to 38 Lug.	44.3 TOP
Detector State	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By	Stand By
REA +5 V	~ +5V (+/- 10%)	4.88	4.91	4.90	4.88	4.92	4.88	4.87	4.90	4.88
REA +3.3 V	~ +3.3V (+/- 10%)	3.23	3.23	3.24	3.24	3.23	3.23	3.23	3.24	3.23
REA +12 V	~ +12V (+/- 10%)	11.84	11.84	11.84	11.86	11.84	11.84	11.83	11.84	11.84
REA -12 V	~ -12V (+/- 10%)	-11.83	-11.83	-11.83	-11.83	-11.83	-11.83	-11.81	-11.81	-11.83
REA +5V Current (A)	Fill as actuals	3.23	3.46	3.47	3.38	3.53	3.53	3.56	3.05	3.47
REA +12V Current (A)	Fill as actuals	0.05	0.05	0.05	0.05	0.05	0.05	0.05	0.05	0.05
REA -12V Current (A)	Fill as actuals	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03	-0.03
REA +3V Current (A)	Fill as actuals	1.07	1.06	1.04	1.06	1.07	1.07	1.06	1.07	1.07
REA FPGA Temp	Fill as actuals	59.43	59.34	59.34	59.43	59.36	59.36	59.42	59.51	59.43
REA DC/DC Temp	Fill as actuals	63.25	63.23	63.25	63.18	63.25	63.27	63.18	63.25	63.25
REA Oscillator Temp	Fill as actuals	61.89	61.97	61.97	61.89	61.89	62.81	61.97	62.89	61.39
CPU +12 V	~ +12V (+/- 10%)	11.78	11.82	11.78	11.78	11.78	11.78	11.78	11.80	11.80
CPU -12 V	~ -12V (+/- 10%)	-11.89	-11.89	-11.89	-11.91	-11.91	-11.91	-11.91	-11.89	-11.91
CPU +12V Current	Fill as actuals	0.10	0.10	0.10	0.10	0.10	0.10	0.10	0.10	0.10
CPU -12V Current	Fill as actuals	-0.05	-0.05	-0.05	-0.05	-0.05	-0.05	-0.05	-0.05	-0.05
STAR 250 temp	Fill as actuals	31.93	32.06	32.42	32.62	32.78	32.83	32.78	32.93	32.96
HVU +15 V	~ +15V (+/- 10%)	14.74	14.73	14.74	14.74	14.74	14.74	14.74	14.74	14.73
HVU +30V	~ +30V (+/- 10%)	29.84	29.83	29.83	29.83	29.84	29.81	29.84	29.83	29.84
HVU -15V	~ -15V (+/- 10%)	-15.37	-15.37	-15.37	-15.39	-15.37	-15.37	-15.37	-15.37	-15.37
HVU +30 V Current	Fill as actuals	0.03	0.03	0.03	0.03	0.03	0.03	0.03	0.03	0.03
HVU +15 V Current	Fill as actuals	0.11	0.11	0.11	0.11	0.11	0.11	0.11	0.11	0.11
HVU -15 V Current	Fill as actuals	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01	-0.01
HVU Anode Voltage	less than 25 V	11.59	11.59	11.59	21.01	11.59	11.59	11.59	11.59	11.59
HVU MCP Voltage	less than 10V	7.81	7.81	7.81	7.81	7.81	7.81	7.81	7.81	7.81
HVU Cathode Voltage	positive voltage (less than 60V)	55.61	55.61	55.61	55.61	55.61	55.61	55.61	55.61	55.61
HVU Temp	Fill as actuals	51.98	52.11	52.11	52.25	52.20	52.32	52.47	52.41	52.47

5.2.2 Temperature Measurements

The temperature of payload was measured as mentioned in 4.2.1. Thermistors were monitored by IIA checkout system. Thermistors were supplied by ISAC thermal group but the temperature curve was not given along with the Thermistors. So, there is a small deviation in temperature measurements of the Thermistors.

At the highest (lowest) temperatures, the temperature given by ISRO-table would have been higher (lower), i.e. if at all the errors have led to small over-testing.

Table 5. 8 Resistance Vs Temperature

Resistance (Ohms)	Temp (deg C) by formula used by IIA during Test	Temp (deg C) by Thermistor table
3640	50	~ 51.5
5350	40	~ 41
8050	30	~ 30.5
12500	20	~ 19.5
19950	10	~ 9.5
32995	0	~ (-2)
56550	-10	~ (-12.5)
101000	-20	~ (-24)
137000	-25	~ (-29)

Appendix A

A.1 Functional Test on FWM

Refer Document “FWM-Functional-testV0.1”.

A.2 Reading Thermistors from IIA test setup

Refer Document “Proce-temp-monitor-1.xls”

Appendix B

B.1 Functional Test on UVIT DS.

Refer document “UVITDS-Functional-Test-Procedure-2.4” to perform the test.

B.2 Performance Test on UVIT DS

Refer document “UVIT-990-00002-PRO Rev 1_5 - Performance Test Procedure” from Routes (CSA) to perform the test.

B.3 List of Cables for TVAC test

For details of Harness, please refer the document “TV-test-EMFM-cable-details0.2.xls”.

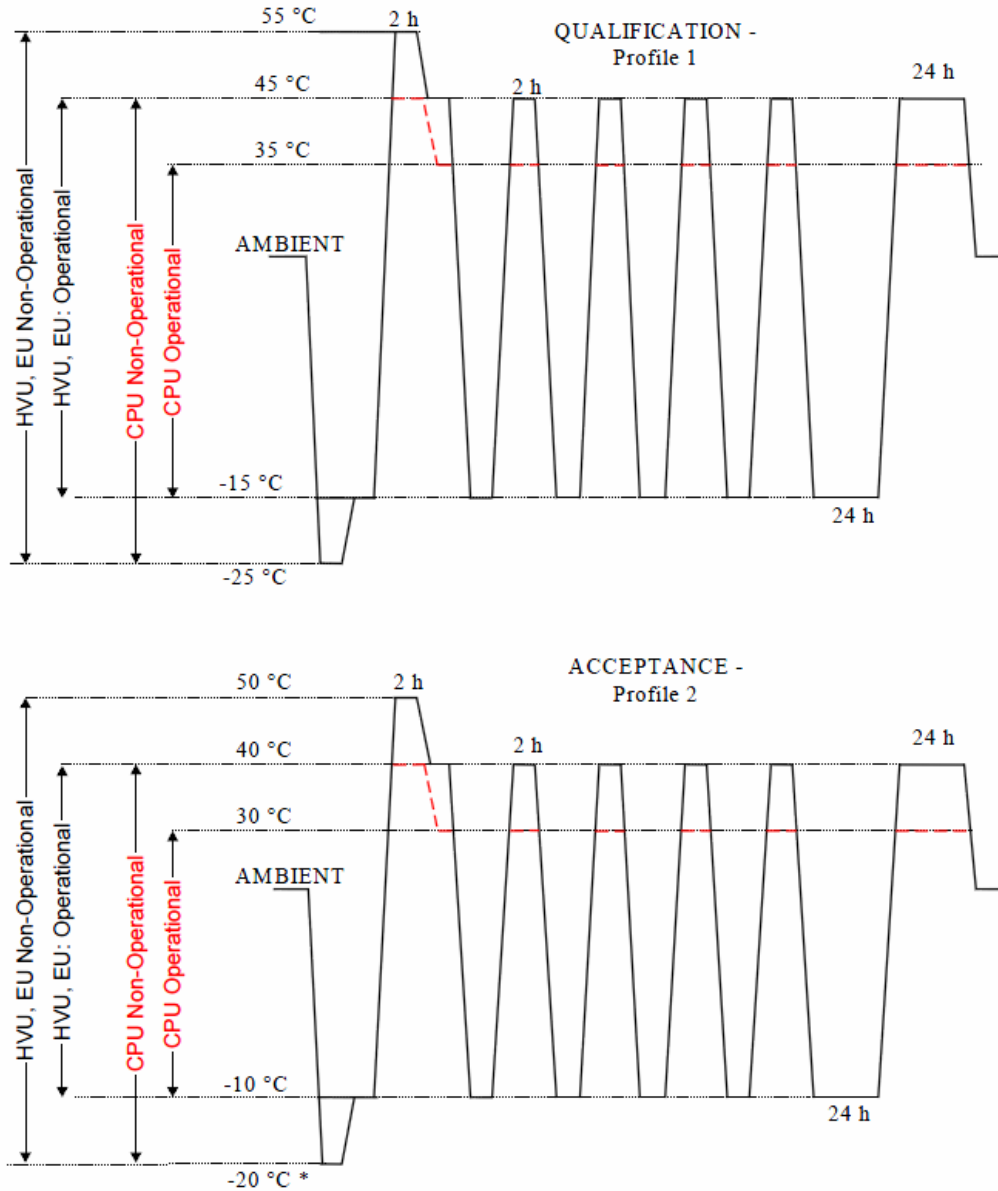
Appendix C

Cleaning, Assembly, and Handling of TVAC Trolley and IR Lamp Cage

1. TVAC trolley will be delivered to ISITE after cleaning with IPA.
2. Unassembled IR Lamp Cage will be delivered to ISITE after cleaning with IPA.
3. In ISITE, IR Lamp cage will be assembled.
4. IR lamps will be mounted on IR Lamp cage.
5. It will be integrated with TVAC trolley, without payload.
6. After this it will be lifted, and placed in TVAC chamber to check it in TVAC chamber.
7. After this whole assembly will be baked to clean the fixtures and TVAC chamber as per the details mentioned in *ASTROSAT Contamination Control notes V0.1*.

Appendix D

TVAC test Profile and Temperature limits, which subsystems have undergone TVAC tests at manufacturers' place.



Appendix-E (Instrumentation Aspects)

Details of the thermistors used for temperature measurement on the payload are given below

Table E. 1 List of Thermistors mounted on EM UVIT Payload

S.No.	Location of Thermistor	Thermistor ID No.	Resistance Value @ ambient (K Ω)	Remarks
1.	MB1	959	11.48	
2.	MB2	4831	11.36	
3.	TT1 Top	4576	11.16	
4.	TT1 Bottom	4807	11.85	
5.	TT2 Top	4462	11.46	
6.	TT2 Bottom	4815	11.4	
7.	TT3 Top	4486	10.98	
8.	TT3 Bottom	4584	11.07	
9.	DMB NUV Top	4483	11.37	
10.	DMB NUV Middle	810	11.15	
11.	NUV Filter Wheel cover	4610	11.39	
12.	CPU	841		
13.	HVU	4572		

Figure E. 1 Position of IR Lamps on the IR Cage (which is mounted around the payload)

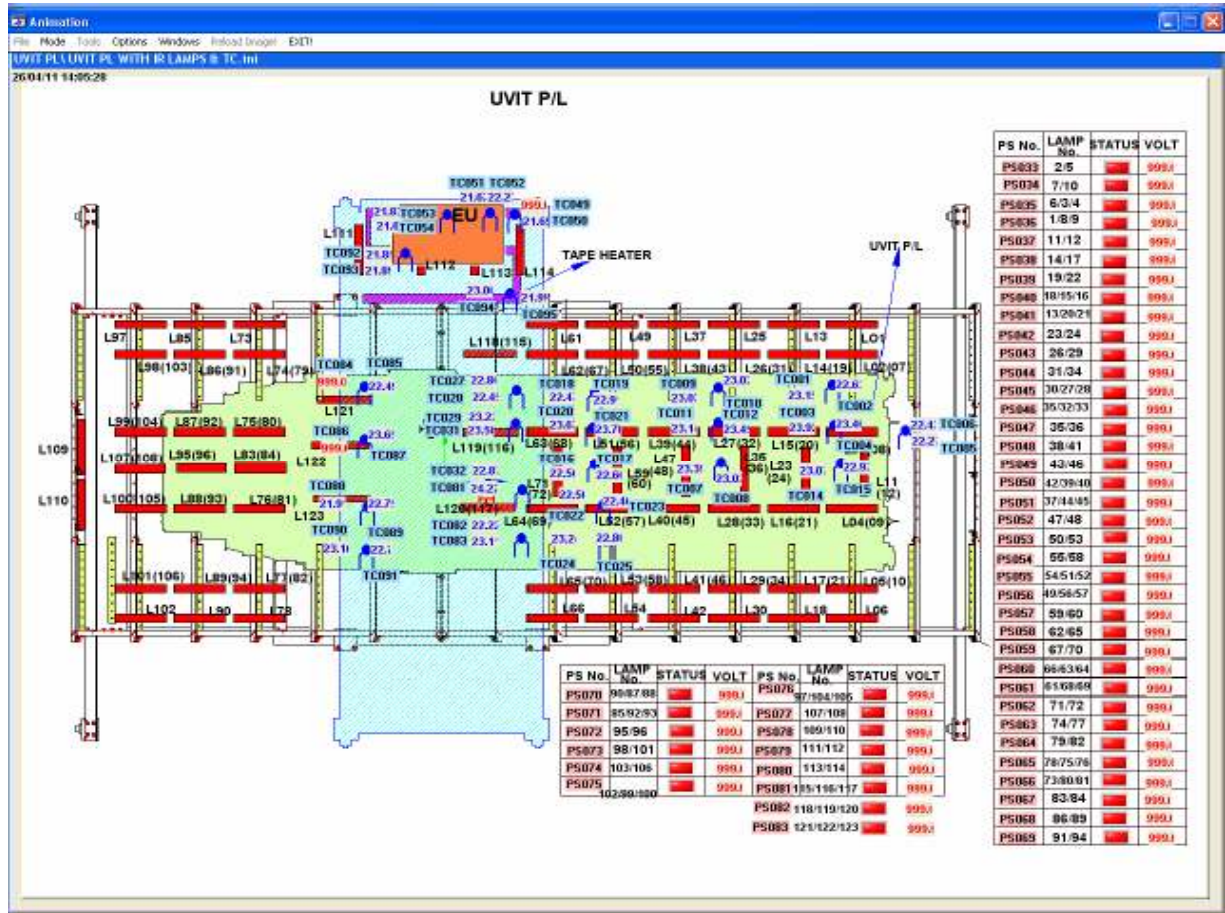


Table E. 2 ELECTRICAL POWERING SCHEME FOR TEST HEATER / IR LAMP

SL. NO.	IR LAMP/ HTRCODE	LOCATION	INSIDE CHAMBER		POWER SUPPLY	
			CON. NO.	PIN NO.	NO	RATING
01	L02/05	UVIT TELESCOPE BAFFEL-1(TC01/02)	TBC05A	A,B	033	60V/8A
02	L07/10	UVIT TELESCOPE BAFFEL-1(TC01/02)	TBC05A	C,D	034	60V/8A
03	L06/03/04	UVIT TELESCOPE BAFFEL-1(TC03/04/05/06)	TBC05A	E,F	035	60V/8A
04	L01/08/09	UVIT TELESCOPE BAFFEL-1(TC03/04/05/06)	TBC05A	G,H	036	60V/8A
05	L11/12	UVIT TELESCOPE BAFFEL-1(TC13/14/05/06)	TBC05A	J,K	037	60V/8A
06	L14/17	UVIT TELESCOPE BAFFEL-1(TC01/02)	TBC05B	A,B	038	60V/8A
07	L19/22	UVIT TELESCOPE BAFFEL-1(TC01/02)	TBC05B	C,D	039	60V/8A
08	L18/15/16	UVIT TELESCOPE BAFFEL-1(TC01/02)	TBC05B	E,F	040	60V/8A
09	L13/20/21	UVIT TELESCOPE BAFFEL-1(TC01/02)	TBC05B	G,H	041	60V/8A
10	L23/24	UVIT TELESCOPE BAFFEL-1(TC13/14)	TBC05B	J,K	042	60V/8A
11	L26/29	UVIT TELESCOPE BAFFEL-2(TC09/10)	TBC05C	A,B	043	60V/8A
12	L31/34	UVIT TELESCOPE BAFFEL-2(TC09/10)	TBC05C	C,D	044	60V/8A
13	L30/27/28	UVIT TELESCOPE BAFFEL-2(TC11/12/07/08)	TBC05C	E,F	045	60V/8A
14	L35/32/33	UVIT TELESCOPE BAFFEL-2(TC09/10)	TBC05C	G,H	046	60V/8A
15	L35/36	UVIT TELESCOPE BAFFEL-2(TC07/08)	TBC05C	J,K	047	60V/8A
16	L38/41	UVIT TELESCOPE BAFFEL-2(TC09/10)	TBC06A	A,B	048	60V/8A
17	L43/46	UVIT TELESCOPE BAFFEL-2(TC09/10)	TBC06A	C,D	049	60V/8A
18	L42/39/40	UVIT TELESCOPE BAFFEL-2(TC11/12)	TBC06A	E,F	050	60V/8A
19	L37/44/45	UVIT TELESCOPE BAFFEL-2(TC09/10)	TBC06A	G,H	051	60V/8A
20	L47/48	UVIT TELESCOPE BAFFEL-2(TC07/08)	TBC06A	J,K	052	60V/8A
21	L50/53	UVIT TELESCOPE TOP(TC17/18)	TBC06B	A,B	053	60V/8A
22	L55/58	UVIT TELESCOPE TOP(TC17/18)	TBC06B	C,D	054	60V/8A
23	L54/51/52	UVIT TELESCOPE TOP(TC19/20/23/24)	TBC06B	E,F	055	60V/8A

Table E.2 ELECTRICAL POWERING SCHEME FOR TEST HEATER / IR LAMP (contd)

SL. NO	IR LAMP/ HTRCODE	LOCATION	INSIDE CHAMBER		POWER SUPPLY	
			CON NO. TDAC(CH.)	PIN NO.	NO.	RATING
24	L49/56/57	UVIT TELESCOPE TOP(TC17/18)	TBC06B	G,H	56	60V/8A
25	L59/60	UVIT TELESCOPE TOP(TC15/16)	TBC06B	J,K	57	60V/8A
26	L62/65	UVIT TELESCOPE TOP/MID(TC17/18/25/26)	TBC06C	A,B	58	60V/8A
27	L67/70	UVIT TELESCOPE TOP/MID(TC17/18/25/26)	TBC06C	C,D	59	60V/8A
28	L66/63/64	UVIT TELESCOPE TOP/MID(TC19/20/23/24)	TBC06C	E,F	60	60V/8A
29	L61/68/69	UVIT TELESCOPE TOP/MID(TC17/18/25/26)	TBC06C	G,H	61	60V/8A
30	L71/72	UVIT TELESCOPE TOP/MID(TC15/16)	TBC06C	J,K	62	60V/8A
31	L74/77	UVIT TELE BOTTOM &PROCESSOR/HV UNIT	TBC07A	A,B	63	60V/8A
32	L79/82	UVIT TELE BOTTOM &PROCESSOR/HV UNIT	TBC07A	C,D	64	60V/8A
33	L78/75/76	UVIT TELE PROCESSOR TOP	TBC07A	E,F	65	60V/8A
34	L73/80/81	UVIT TELE PROCESSOR BOT	TBC07A	G,H	66	60V/8A
35	L83/84	UVIT TELE PROCESSOR TOP	TBC07A	J,K	67	60V/8A
36	L86/89	UVIT PROCESSOR/HV UNIT SIDE	TBC07B	A,B	68	60V/8A
37	L91/94	UVIT PROCESSOR/HV UNIT SIDE	TBC07B	C,D	69	60V/8A
38	L90/87/88	UVIT PROCESSOR/HV UNIT TOP	TBC07B	E,F	70	60V/8A
39	L85/92/93	UVIT PROCESSOR/HV UNIT BOT	TBC07B	G,H	71	60V/8A
40	L95/96	UVIT PROCESSOR/HV UNIT TOP	TBC07B	J,K	72	60V/8A
41	L98/101	UVIT PROCESSOR/HV UNIT SIDE	TBC07C	A,B	73	60V/8A
42	L103/106	UVIT PROCESSOR/HV UNIT SIDE	TBC07C	C,D	74	60V/8A
43	L102/99/100	UVIT PROCESSOR/HV UNIT TOP	TBC07C	E,F	75	60V/8A
44	L97/104/105	UVIT PROCESSOR/HV UNIT BOT	TBC07C	G,H	76	60V/8A
45	L107/108	UVIT PROCESSOR/HV UNIT TOP	TBC07C	J,K	77	60V/8A
46	L109/110	HVU BOX END	TBC08A	A,B	78	60V/8A
47	L111/112	ABOVE EU BOX	TBC08A	C,D	79	60V/8A
48	L113/114	ABOVE FWDE BOX	TBC08A	E,F	80	60V/8A
49	L115/116/117	UVIT TELE MID(UNDER	TBC08A	G,H	81	60V/8A
50	L118/119/120	UVIT TELE MID(TOP) (TC25/26/27/28/29/30)	TBC08A	J,K	82	60V/8A
51	L121/122/123	UVIT TELE BOT(TOP) (TC33/34/35/36/37/38)	TBC08B	A,B	83	60V/8A

Table E.2 ELECTRICAL POWERING SCHEME FOR TEST HEATER / IR LAMP (contd)

SL. NO.	IR LAMP/ HTRCODE	LOCATION	INSIDE CHAMBER		POWER SUPPLY	
			CON. NO.	PIN NO.	NO.	RATING
52	PLT01	ON AL. PLATE	TBC01	A,B	001	60V/4A
53	PLT02	ON AL. PLATE	TBC01	C,D	002	60V/4A
53			TBC01	E,F	003	60V/4A
54			TBC01	G,H	004	60V/4A
55			TBC01	J,K	005	60V/4A
56			TBC01	L,M	006	60V/4A

Table E. 3 : List of thermocouples

Page Display System - 1

Page

PAGE DISPLAY SYSTEM - 1

UNIT

Test Type: ACCEPTANCE TEST

Page Name: 1. ALL TC PAGE-1

Test Mode: Ambient

Channel Name	Channel Description	Limits (High/Low)	Units	26/04/11 13:33:27	Channel Name	Channel Description	Limits (High/Low)	Units	26/04/11 13:33:27
TC001	FUV BAFFLE-1 SIDE-M	35.0	Deg C	22.99	TC002	FUV BAFFLE-1 SIDE-R	35.0	Deg C	22.46
TC003	FUV BAFFLE-1 TOP-M	35.0	Deg C	23.74	TC004	FUV BAFFLE-1 TOP-R	35.0	Deg C	23.24
TC005	MUV BAFFLE-1 SIDE-M	35.0	Deg C	22.09	TC006	MUV BAFFLE-1 SIDE-R	35.0	Deg C	22.30
TC007	MUV BAFFLE-1 TOP-M	35.0	Deg C	23.19	TC008	MUV BAFFLE-1 TOP-R	35.0	Deg C	22.86
TC009	FUV BAFFLE-2 SIDE-M	35.0	Deg C	22.86	TC010	FUV BAFFLE-2 SIDE-R	35.0	Deg C	22.83
TC011	FUV BAFFLE-2 TOP-M	35.0	Deg C	22.97	TC012	FUV BAFFLE-2 TOP-R	35.0	Deg C	23.31
TC014	MUV BAFFLE-2 SIDE-M	35.0	Deg C	22.89	TC015	MUV BAFFLE-2 SIDE-R	35.0	Deg C	22.74
TC016	MUV BAFFLE-2 TOP-M	35.0	Deg C	22.37	TC017	MUV BAFFLE-2 TOP-R	35.0	Deg C	22.49
TC018	FUV TELE-TOP SIDE-M	35.0	Deg C	22.29	TC019	FUV TELE-TOP SIDE-R	35.0	Deg C	22.73
TC020	FUV TELE-TOP TOP-M	35.0	Deg C	23.48	TC021	FUV TELE-TOP TOP-R	35.0	Deg C	23.62
TC022	MUV TELE-TOP SIDE-M	35.0	Deg C	22.34	TC023	MUV TELE-TOP SIDE-R	35.0	Deg C	22.29
TC024	MUV TELE-TOP TOP-M	35.0	Deg C	23.09	TC025	MUV TELE-TOP TOP-R	35.0	Deg C	22.64
TC027	FUV TELE-MID SIDE-M	35.0	Deg C	22.67	TC028	FUV TELE-MID SIDE-R	35.0	Deg C	22.27
TC029	FUV TEL F.MID TOP-M	35.0	Deg C	23.07	TC031	FUV TEL F.MID TOP-R	35.0	Deg C	23.47
TC032	MUV TELE-MID SIDE-M	35.0	Deg C	22.72	TC049	EU PKG NBY LUG M	50/-15	Deg C	Open
TC050	EU PKG NBY LUG R	50/-15	Deg C	21.42	TC051	EU PKG LUG M	50/-15	Deg C	21.42
TC052	EU PKG LUG R	50/-15	Deg C	22.08	TC053	EU PKG TOP M	50/-15	Deg C	21.56
TC054	EU PKG TOP R	50/-15	Deg C	21.38	TC081	MUV TELE-MID SIDE-R	35.0	Deg C	Open
TC082	MUV TELE-MID TOP-M	35.0	Deg C	22.05	TC083	MUV TELE-MID TOP-R	35.0	Deg C	22.94
TC084	FUV TELE-BOT SIDE-M	35.0	Deg C	Open	TC085	FUV TELE-BOT SIDE-R	35.0	Deg C	22.31
TC086	FUV TELE-BOT TOP-M	35.0	Deg C	Open	TC087	FUV TELE-BOT TOP-R	35.0	Deg C	23.51
TC088	MUV TELE-BOT SIDE-M	35.0	Deg C	21.73	TC089	MUV TELE-BOT SIDE-R	35.0	Deg C	22.61
TC090	MUV TELE-BOT TOP-M	35.0	Deg C	22.95	TC091	MUV TELE-BOT TOP-R	35.0	Deg C	22.54
TC092	EU SINK PLATE HTR1M	50/-15	Deg C	21.67	TC093	EU SINK PLATE HTR1R	50/-15	Deg C	21.69
TC094	EU SINK PLATE HTR2M	50/-15	Deg C	22.74	TC095	EU SINK PLATE HTR2R	50/-15	Deg C	21.70

Orbit Monitor: None

Orbit Position: None

Total Power: 0.000 KWatts

ALARM

PSPU GCO FAC

SYSTEM HEALTH

TSPU1 TSPU2 TSPU3 TSPU4 DOO FAC